

US010366776B2

(12) **United States Patent**
Oh et al.

(10) **Patent No.:** **US 10,366,776 B2**
(45) **Date of Patent:** **Jul. 30, 2019**

(54) **MEMORY SYSTEM FOR EFFECTIVELY ORGANIZING SUPER MEMORY BLOCK AND OPERATING METHOD THEREOF**

G11C 16/3495; G11C 16/0483; G11C 16/3459; G11C 5/04; G11C 7/24; G11C 11/5641; G06F 3/064; G06F 3/0619
USPC 365/200, 201, 185.09, 185.11, 185.12, 365/185.23

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See application file for complete search history.

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(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 9 days.

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(21) Appl. No.: **15/695,279**

(22) Filed: **Sep. 5, 2017**

(65) **Prior Publication Data**

US 2018/0151251 A1 May 31, 2018

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(30) **Foreign Application Priority Data**

Nov. 29, 2016 (KR) 10-2016-0160093

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(51) **Int. Cl.**

G11C 29/00	(2006.01)
G06F 3/06	(2006.01)
G11C 29/42	(2006.01)
G11C 29/44	(2006.01)

(57) **ABSTRACT**

A memory system may include: a memory device including a plurality of memory blocks configured in a plurality of super memory blocks; and a controller suitable for detecting two or more bad super memory blocks each including at least one bad block among the super memory blocks, selecting at least one victim super memory block among the bad super memory blocks, and replacing the at least one bad block in each remaining bad super memory block with at least one normal block of the victim super memory block.

(52) **U.S. Cl.**

CPC **G11C 29/82** (2013.01); **G06F 3/064** (2013.01); **G06F 3/0619** (2013.01); **G11C 29/42** (2013.01); **G11C 29/4401** (2013.01); **G11C 29/76** (2013.01)

(58) **Field of Classification Search**

CPC G11C 29/52; G11C 29/08; G11C 29/82; G11C 29/4401; G11C 29/76; G11C 29/883; G11C 29/785; G11C 16/249;

20 Claims, 15 Drawing Sheets

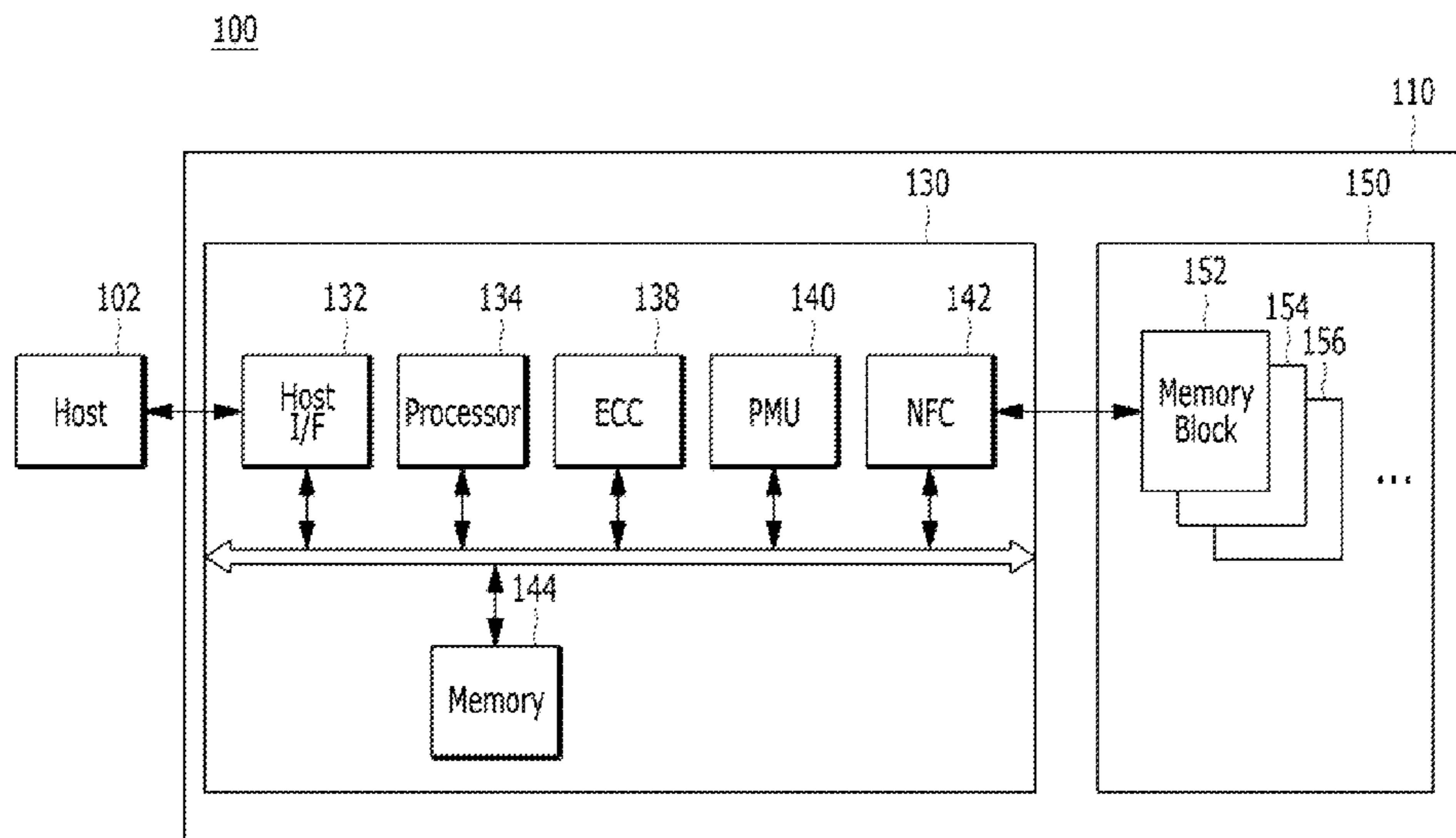


FIG. 1

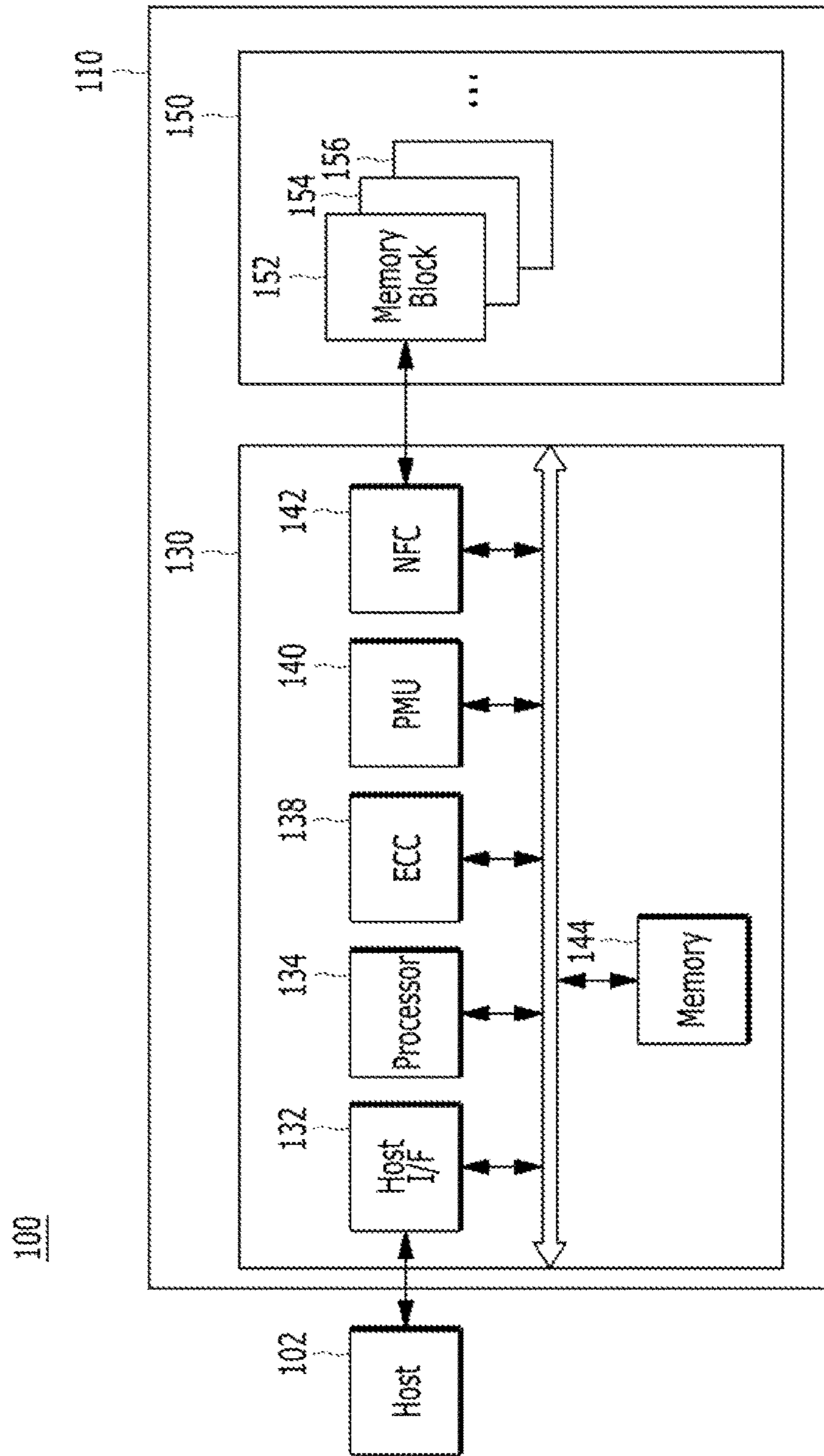


FIG. 2

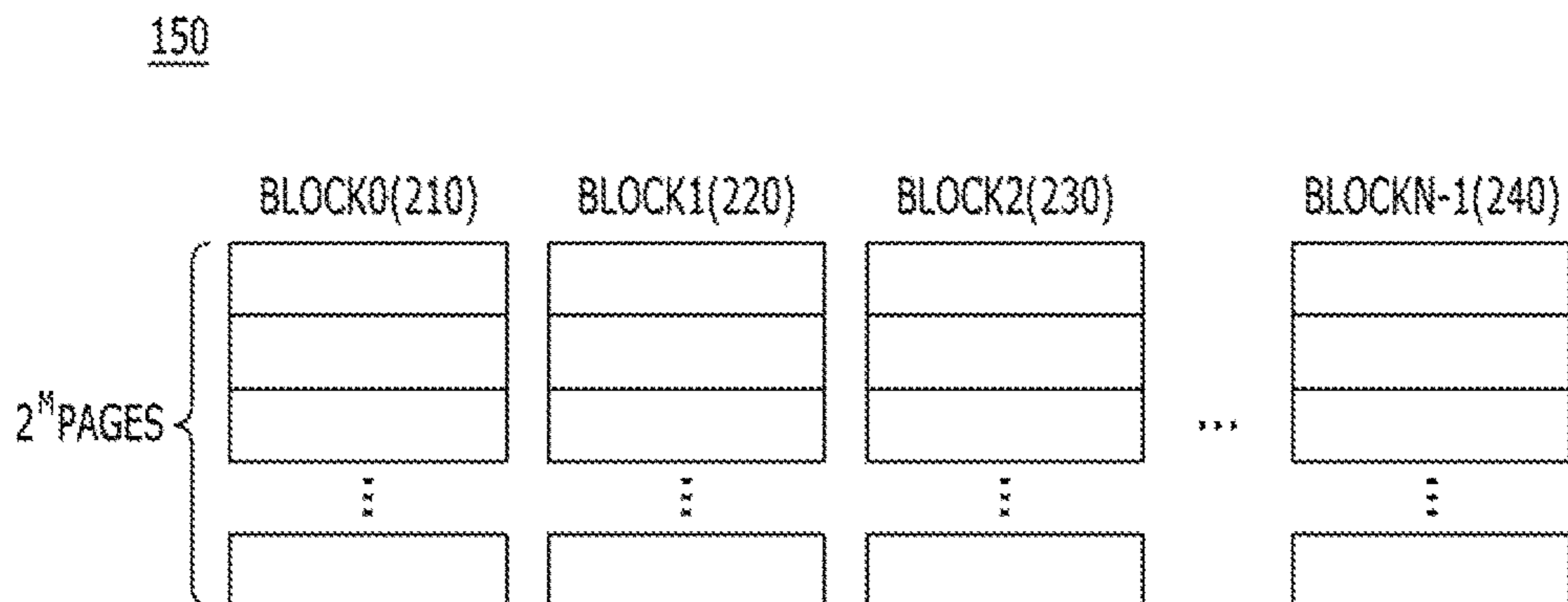


FIG. 3

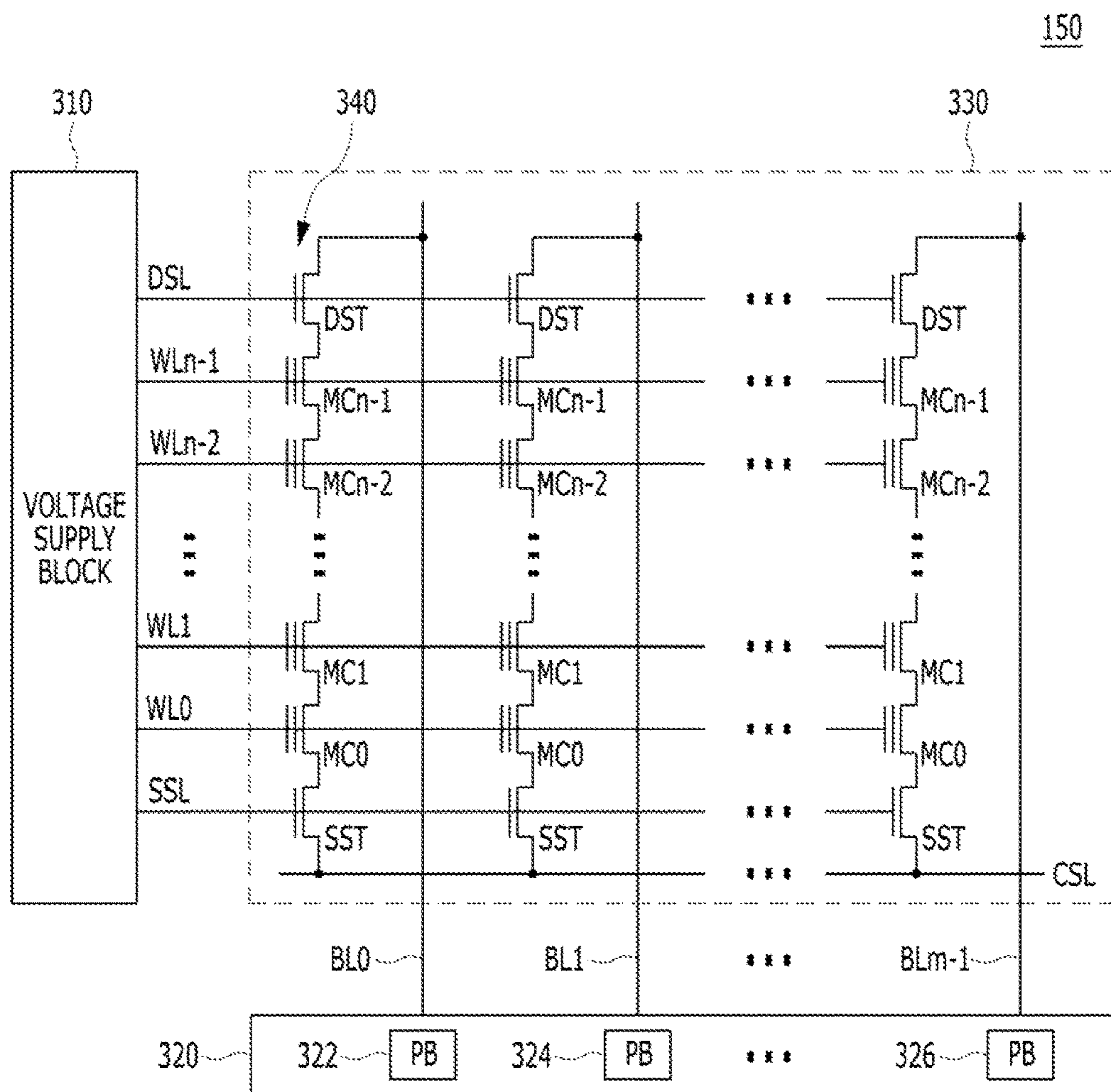


FIG. 4

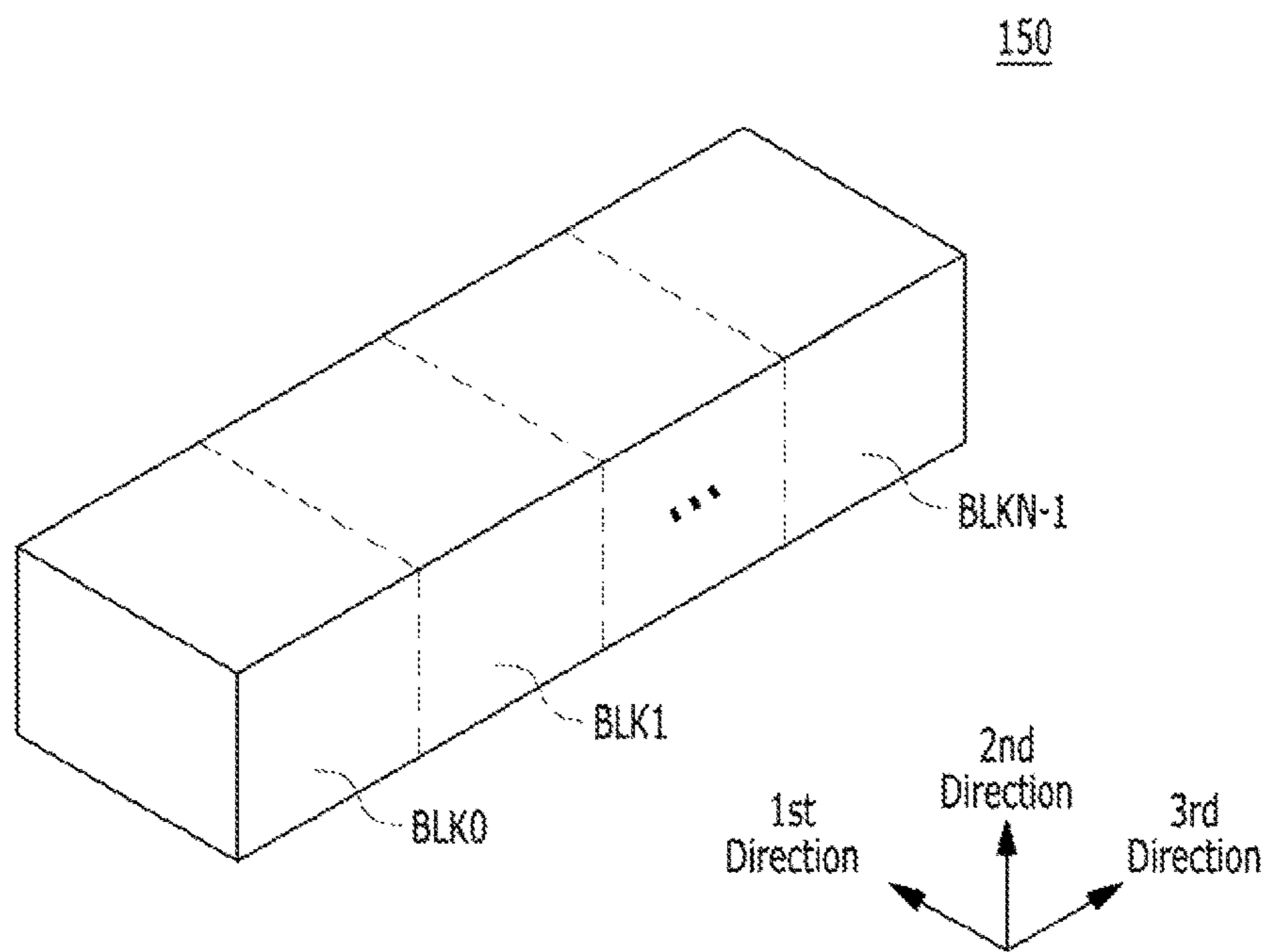


FIG. 5A

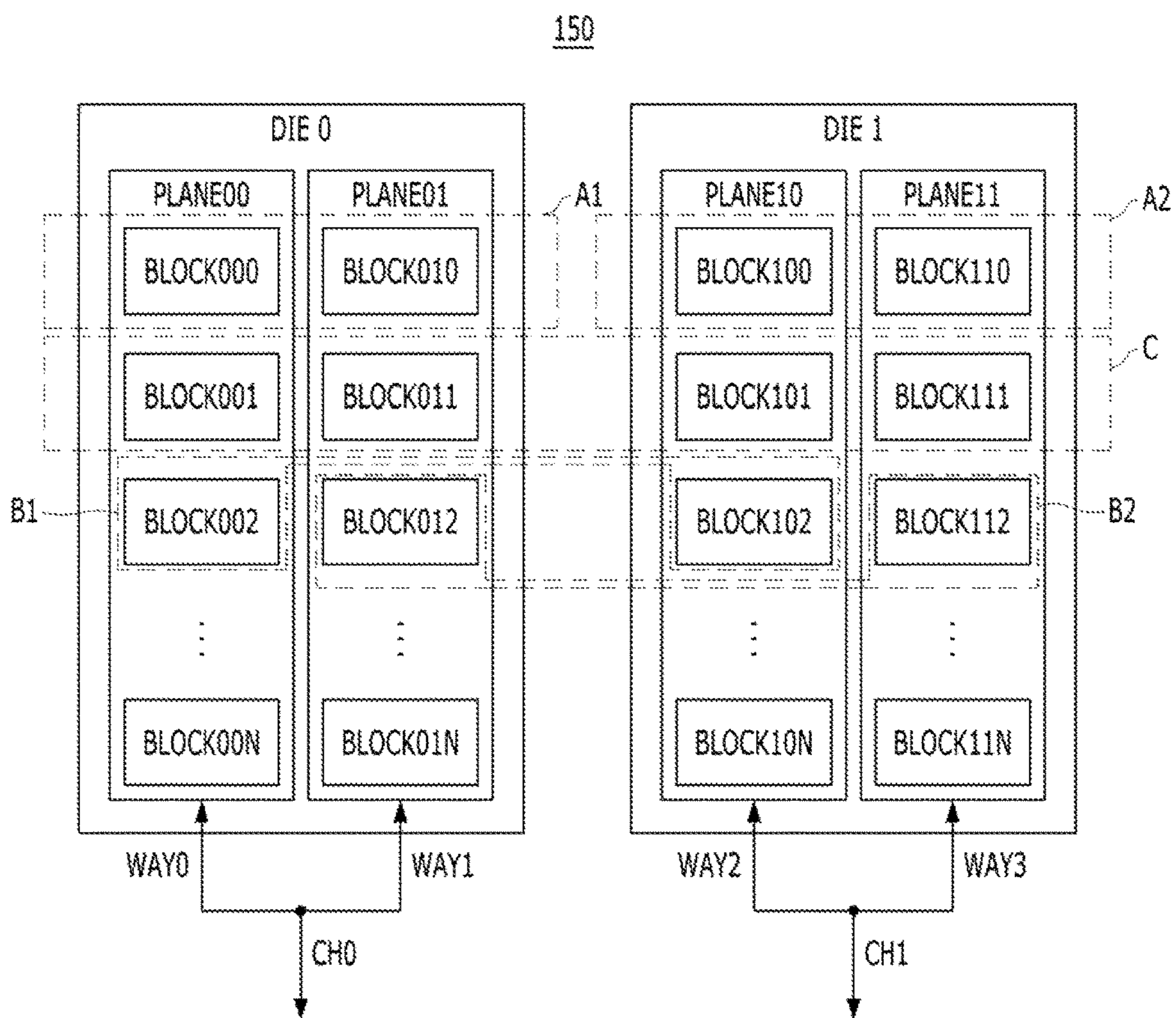


FIG. 5B

150

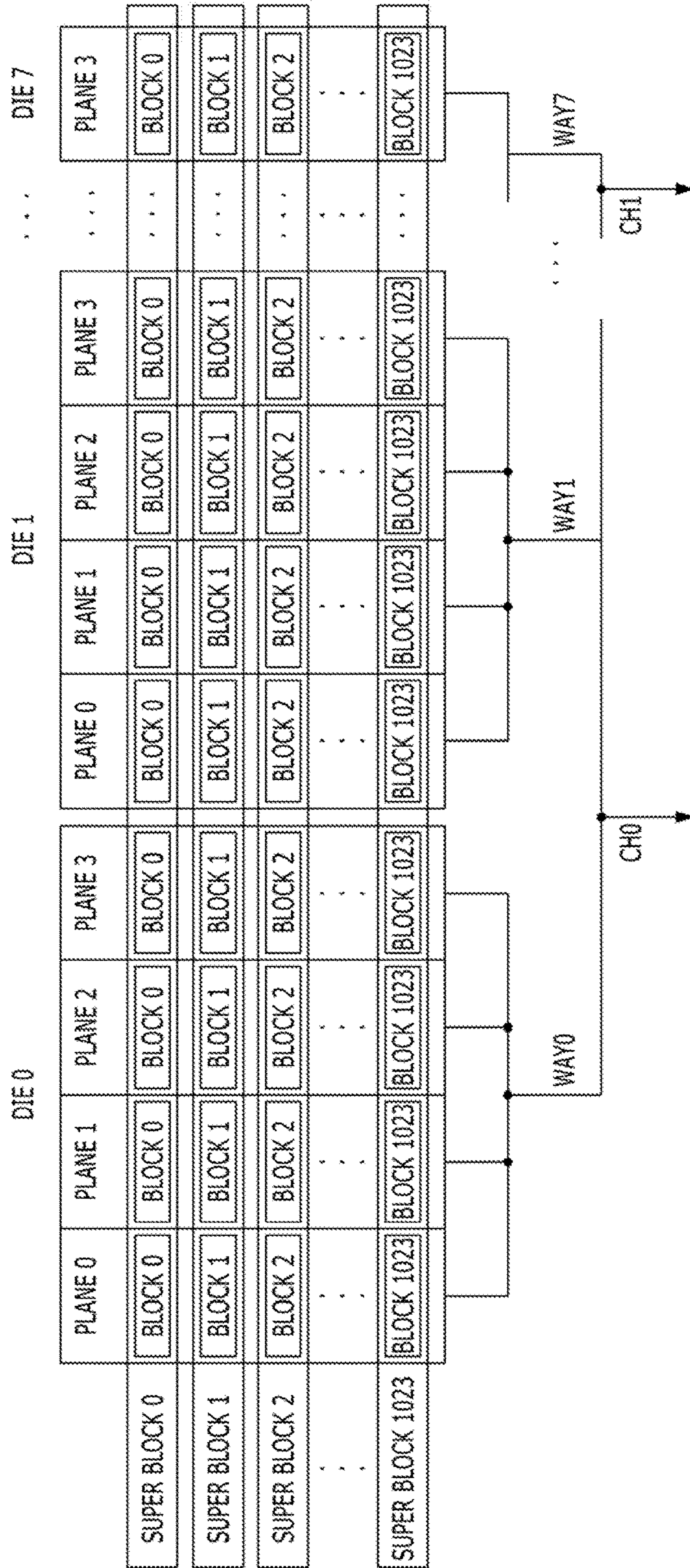


FIG. 6

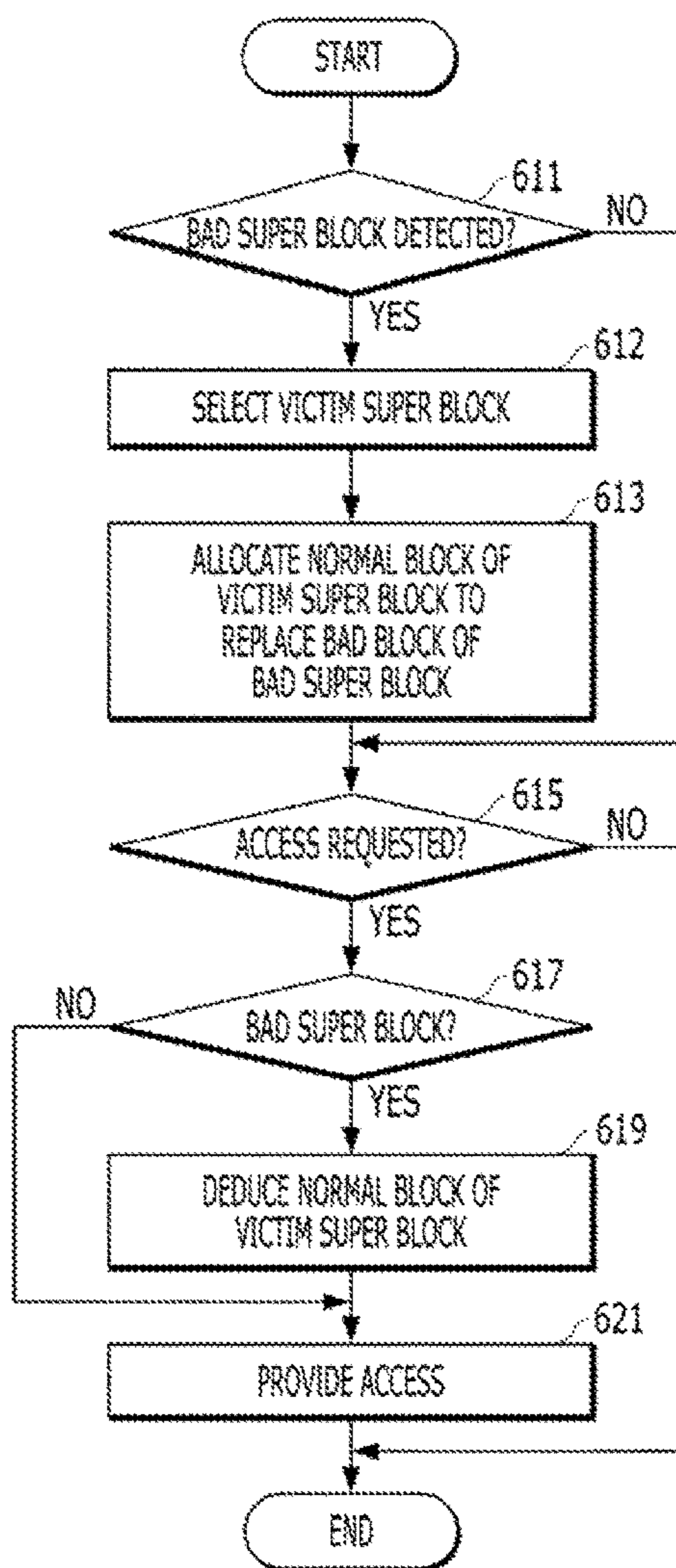


FIG. 7

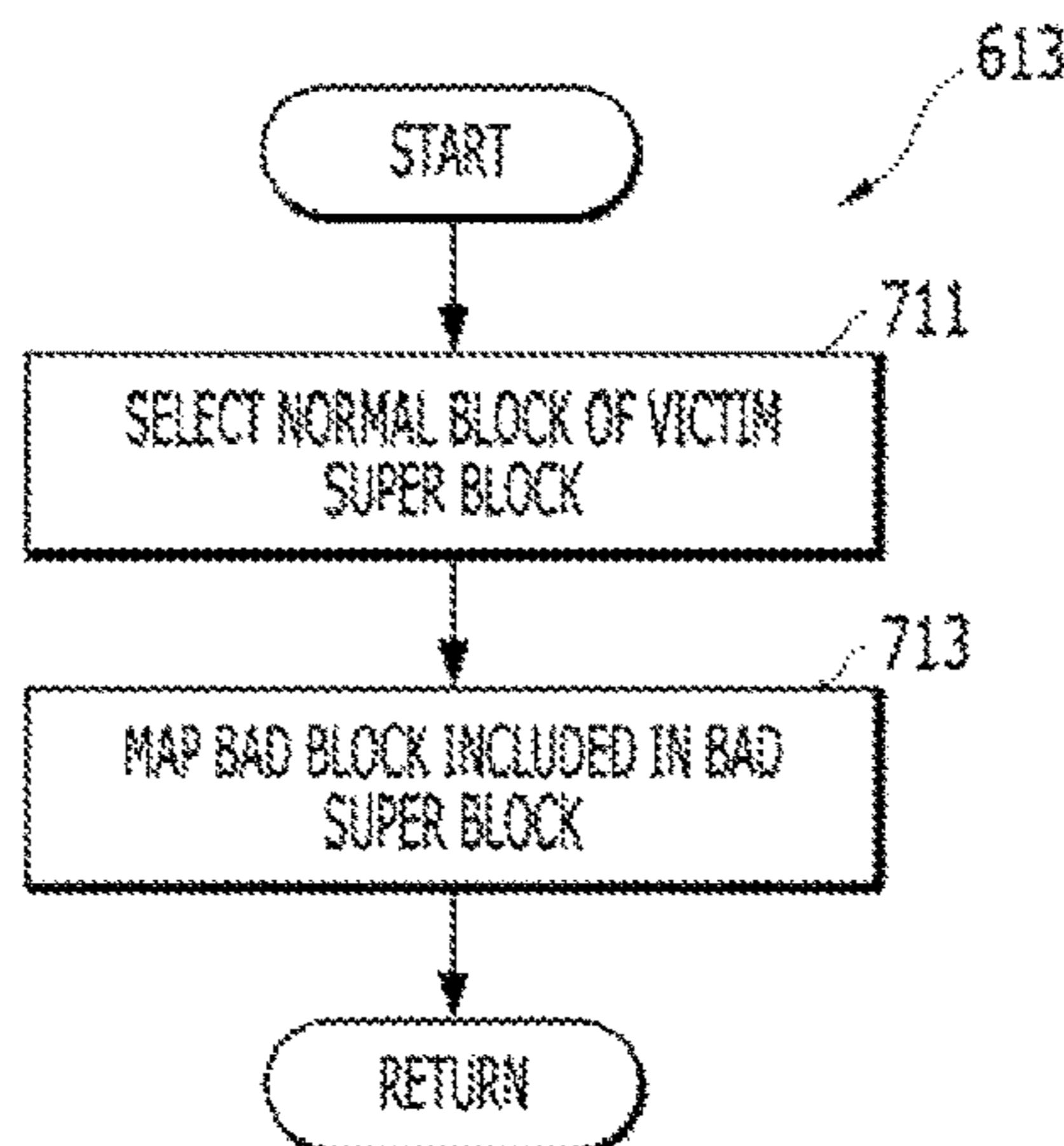


FIG. 9

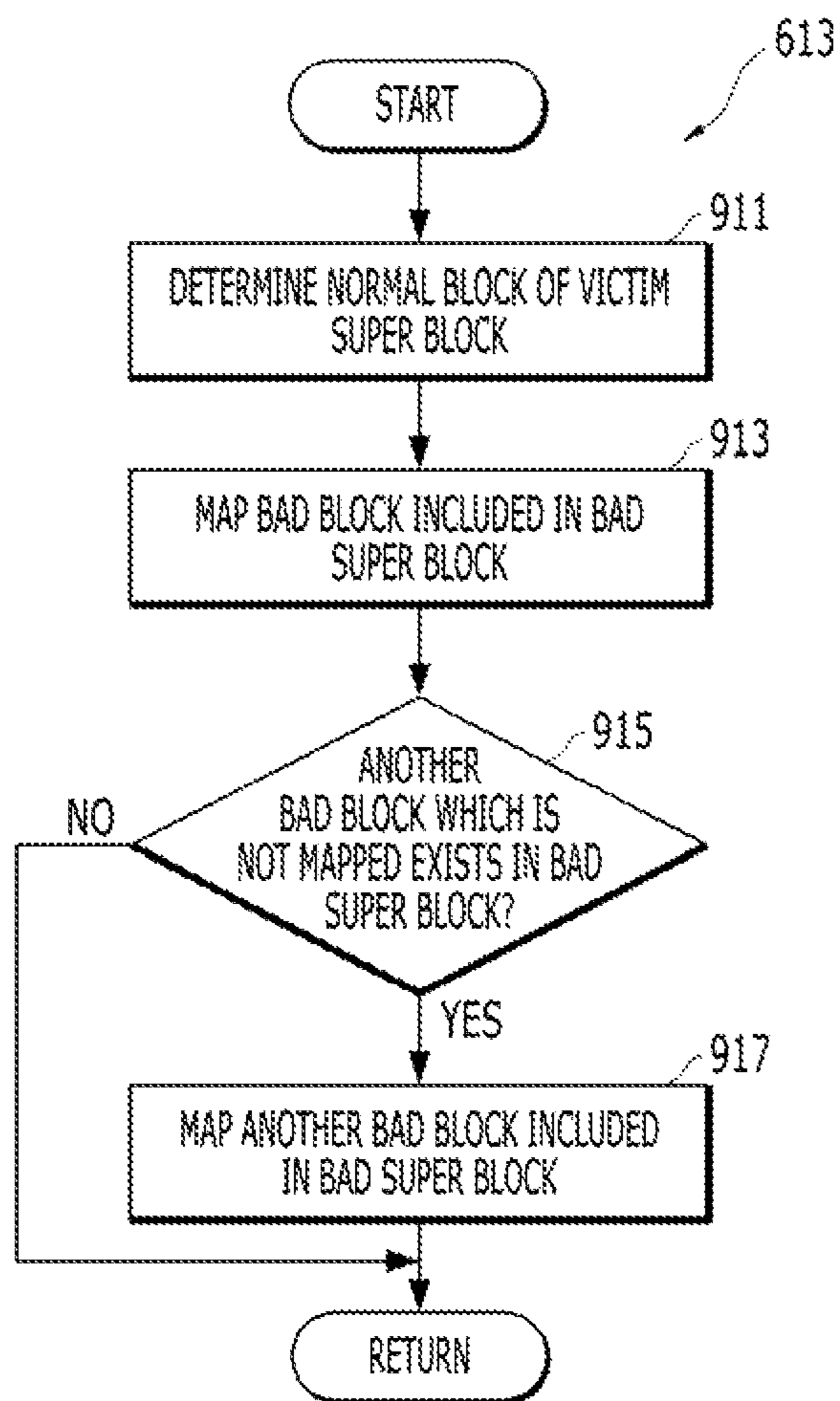


FIG. 11

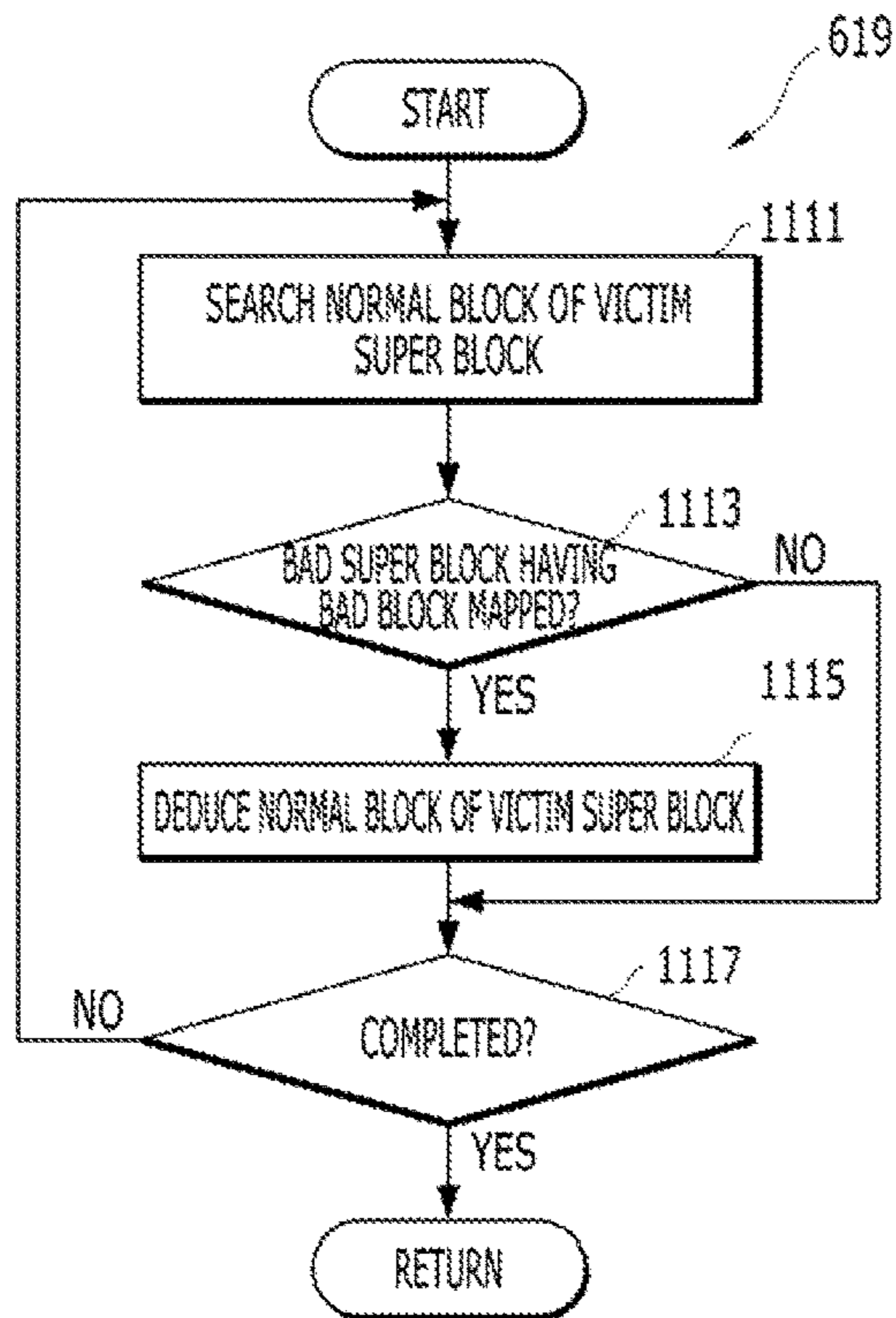


FIG. 12

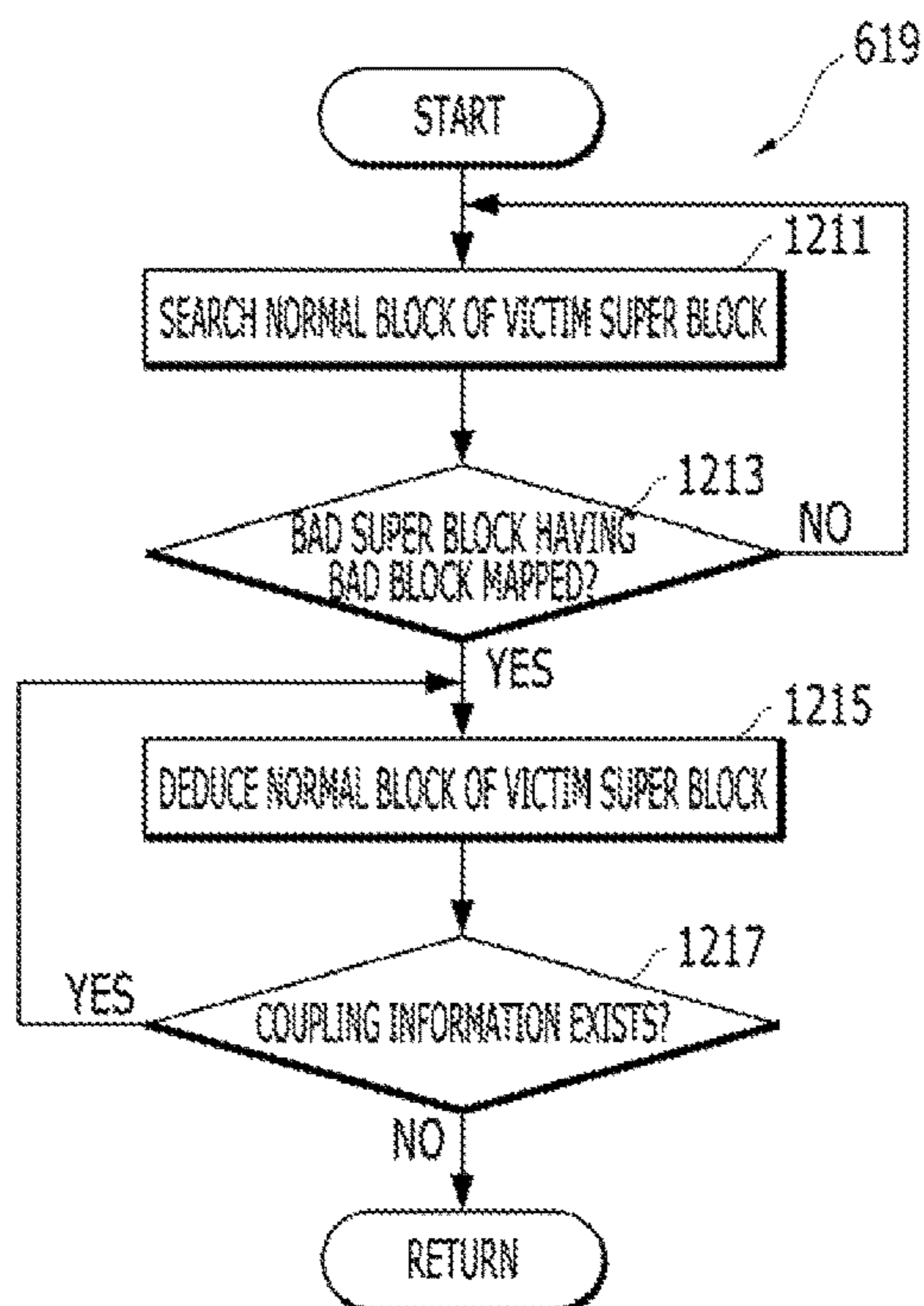


FIG. 13

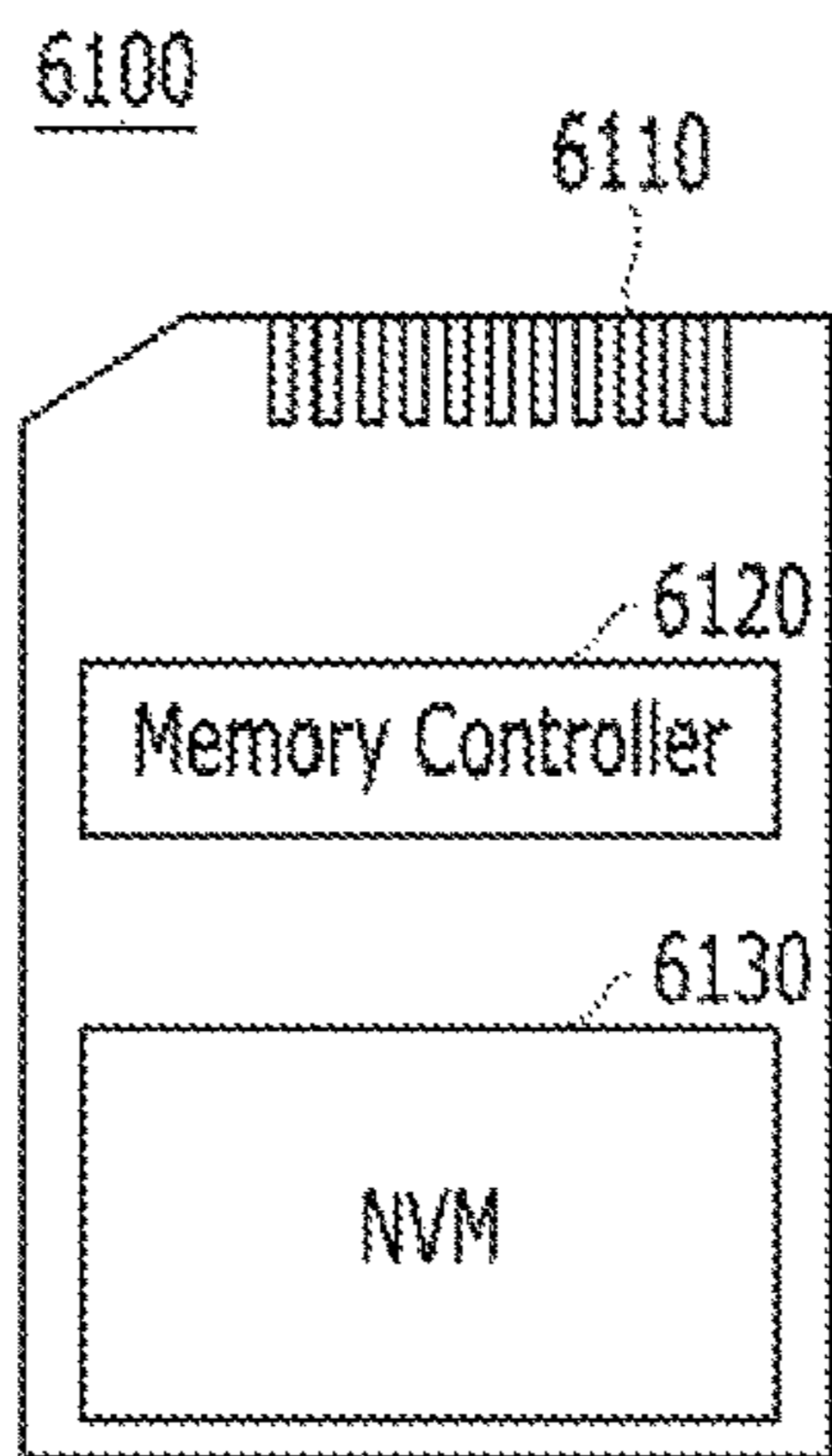


FIG. 14

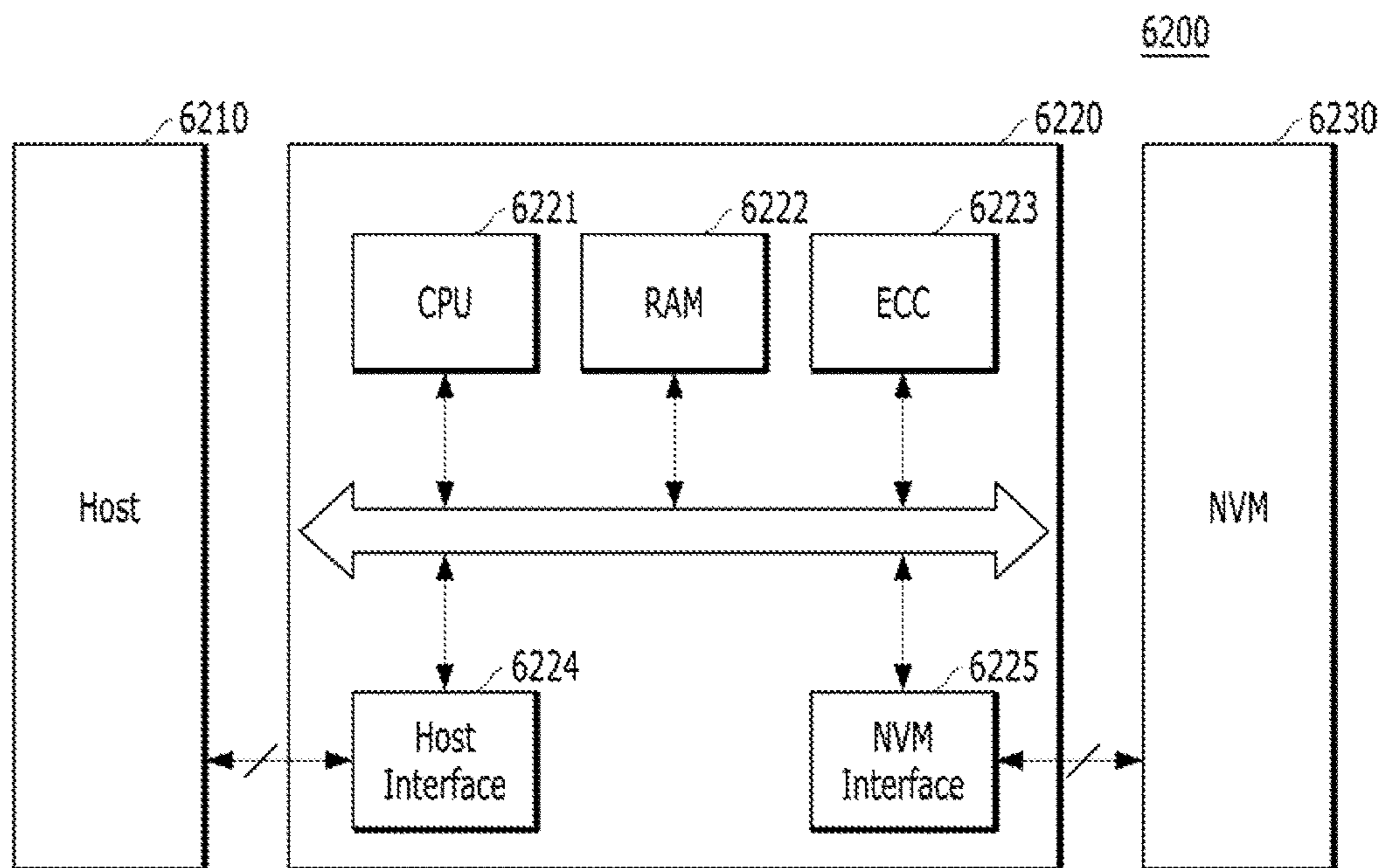


FIG. 15

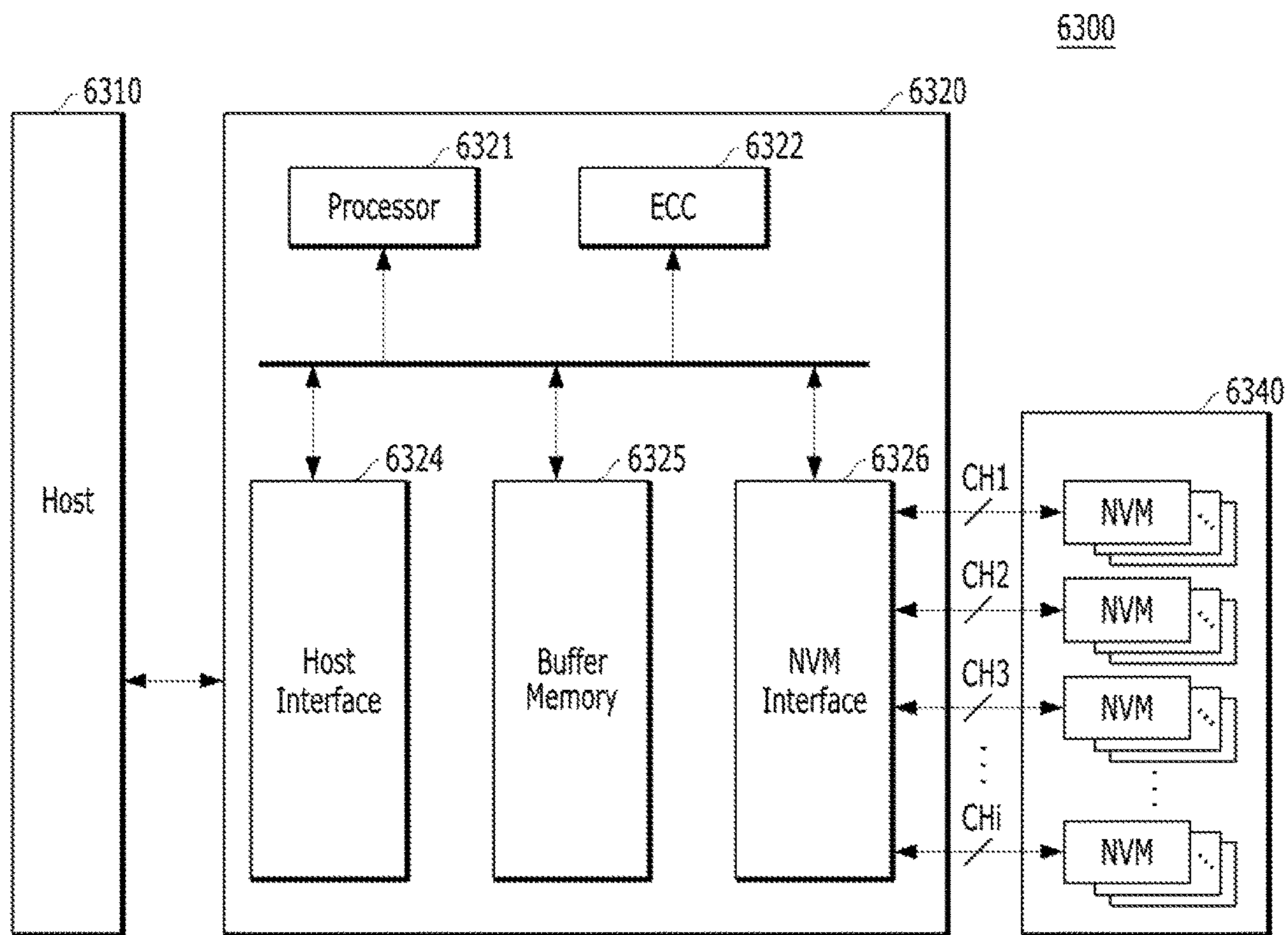


FIG. 16

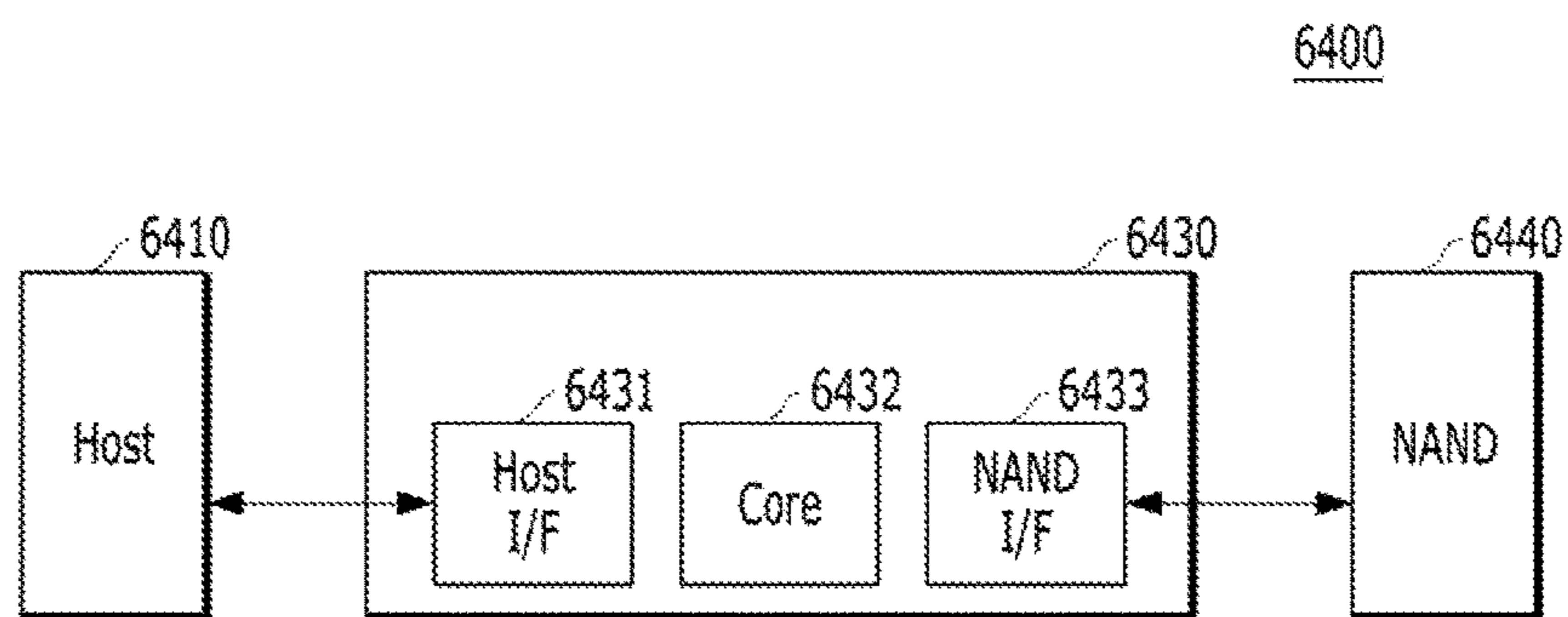


FIG. 17

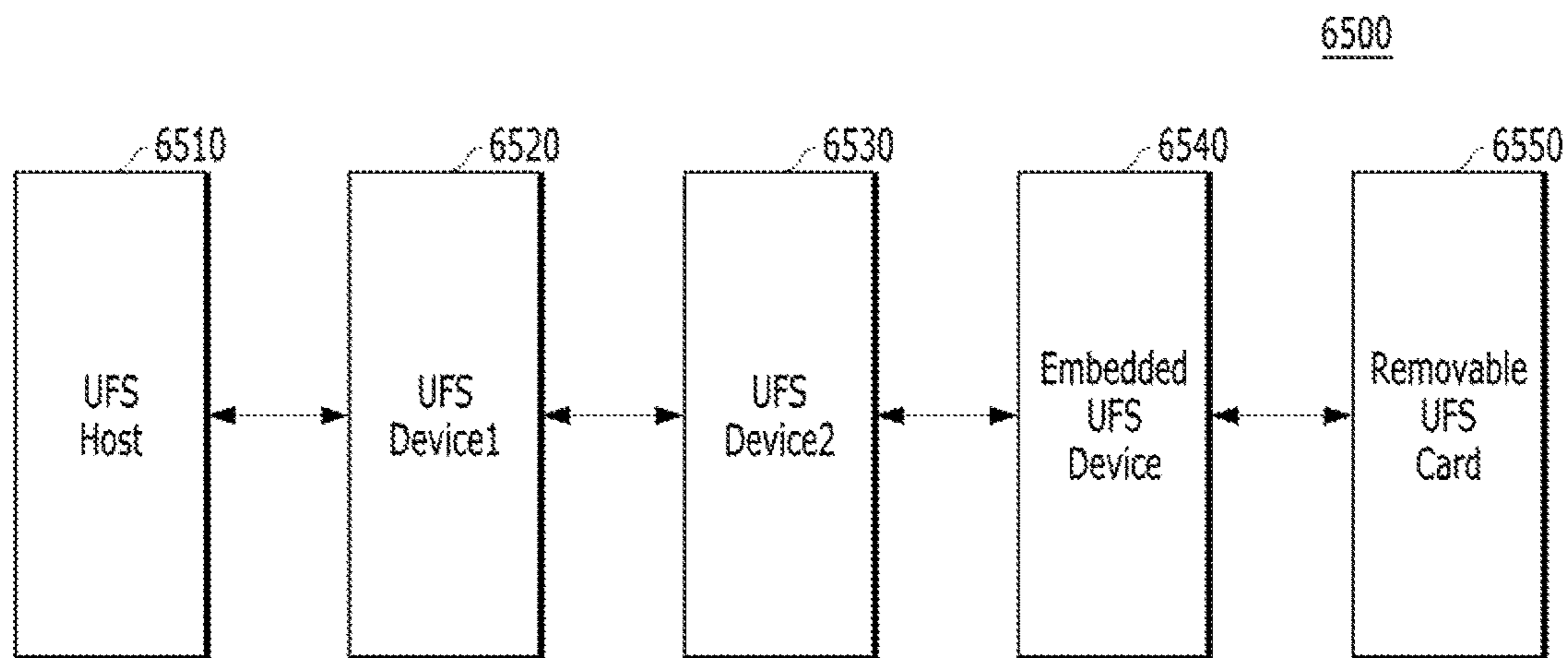
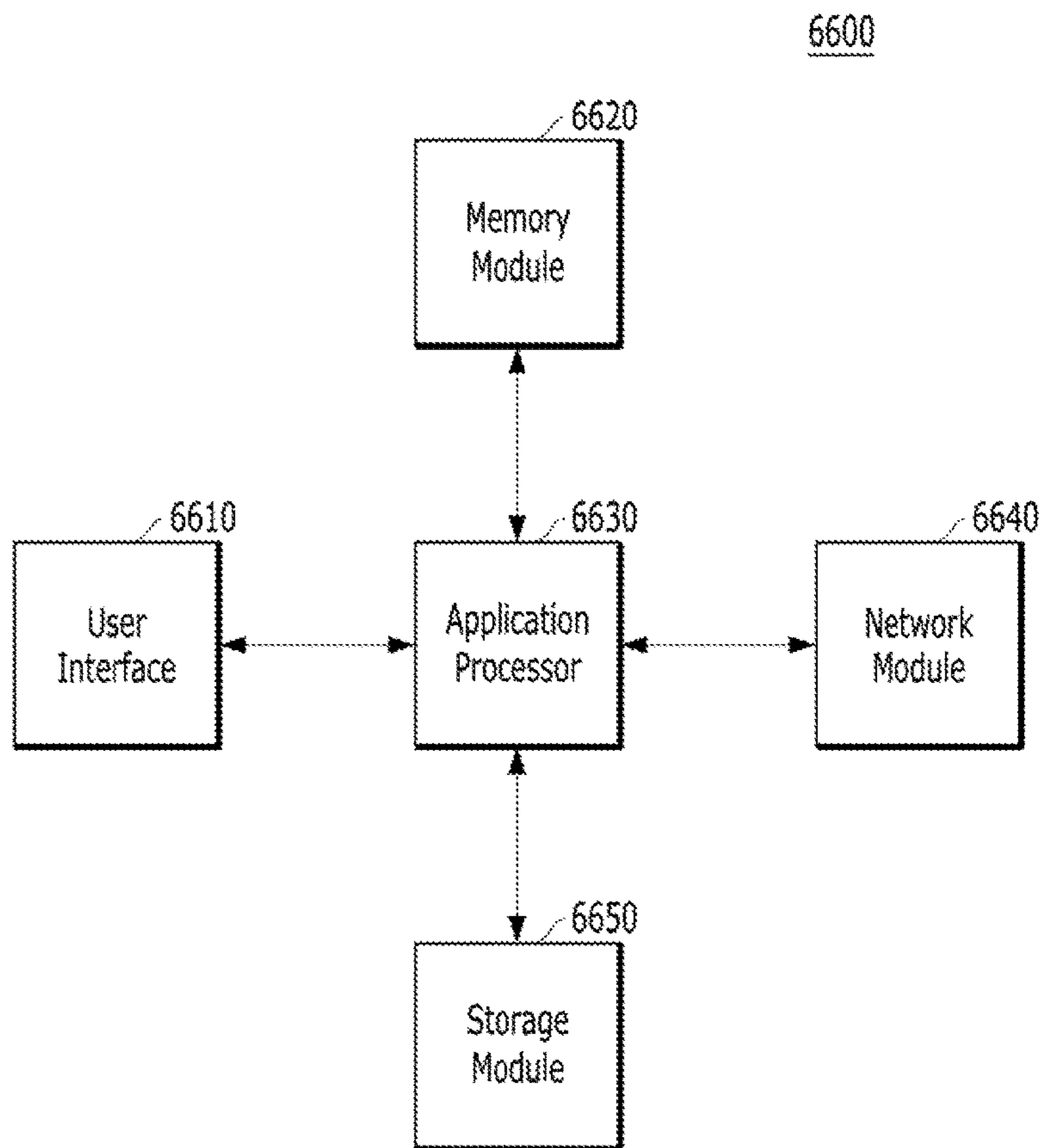


FIG. 18



**MEMORY SYSTEM FOR EFFECTIVELY
ORGANIZING SUPER MEMORY BLOCK
AND OPERATING METHOD THEREOF**

CROSS-REFERENCE TO RELATED
APPLICATION

This application claims priority under 35 U.S.C. § 119 to Korean Patent Application No. 10-2016-0160093 filed on Nov. 29, 2016 in the Korean Intellectual Property Office, the disclosure of which is incorporated herein by reference in its entirety.

TECHNICAL FIELD

Exemplary embodiments relate to a memory system including a memory device and an operating method thereof.

DISCUSSION OF THE RELATED ART

The computer environment paradigm has changed to ubiquitous computing systems that can be used anytime and anywhere. Due to this, use of portable electronic devices such as mobile phones, digital cameras, and notebook computers has rapidly increased. These portable electronic devices generally use a memory system having one or more memory devices for storing data. A memory system may be used as a main memory or an auxiliary memory of a portable electronic device.

Memory systems provide excellent stability, durability, high information access speed, and low power consumption because they have no moving parts. Examples of memory systems having such advantages include universal serial bus (USB) memory devices, memory cards having various interfaces, and solid state drives (SSD).

In a memory system, a memory device may be configured by a plurality of blocks, some of which may be or become bad blocks. Typically, a memory system may swap a bad block with a normal block, to provide access to the normal block in response to a request of access to the bad block. However, an excessively large storage space is required for storing mapping information relating to the swapping of bad blocks and normal blocks in a memory system.

SUMMARY

Various embodiments of the present invention are directed to a memory system exhibiting a substantially improved efficiency in the use of a memory device, and an operating method thereof.

In an embodiment, a memory system may include: a memory device including a plurality of memory blocks configured in a plurality of super memory blocks; and a controller suitable for detecting two or more bad super memory blocks each including at least one bad block among the super memory blocks, selecting at least one victim super memory block among the bad super memory blocks, and replacing the at least one bad block in each remaining bad super memory block with at least one normal block of the victim super memory block.

The controller may generate a bad group table indicating a mapping relationship between the at least one bad block of each of the remaining bad super memory blocks and the corresponding normal blocks of the at least one victim super memory block which replace the at least one bad block of each of the remaining bad super memory blocks.

In response to a request of access to at least one of the two or more bad super memory blocks, the controller may provide access to the normal blocks replacing the bad blocks in the access-requested bad super memory blocks according to the mapping relationship.

The controller may replace the bad blocks with the normal blocks having the same physical locations as the bad blocks in the bad super memory blocks, and the physical location may be of a plane level in the memory device.

The bad group table may include at least one entry respectively representing the at least one victim super memory block, for the at least one entry, the bad group table may include a plurality of location fields respectively representing physical locations of memory blocks of a corresponding victim super memory block, and each location field representing the normal block in the at least one victim super memory block may have been an address value of the bad super memory block having the bad block, which is replaced by the normal block represented thereby.

The bad group table may include at least one row and a plurality of columns configured in the form of a matrix, and the at least one victim super memory block may correspond to one row, memory blocks included in the at least one victim super memory block may correspond to the columns, and the bad blocks included in the bad super memory blocks may be mapped to the columns.

In response to the request, the controller may provide access to the normal blocks replacing the bad blocks in the access-requested bad super memory blocks by: searching the address values of the access-requested bad super memory block on an entry-by-entry basis in the bad group table; and identifying the normal blocks replacing the access-requested bad blocks through the physical locations of the normal blocks indicated by the location fields having the address values of the access-requested bad super memory blocks.

The bad group table may include at least one entry representing the at least one victim super memory block, for the at least one entry, the bad group table may include a plurality of location fields respectively representing physical locations of memory blocks of the at least one victim super memory block and each location field including first and second sub-fields, the first sub-field, a corresponding location field of which represents the normal block in the at least one victim super memory block, may have been an address value of the bad super memory block having the bad block, which is replaced by the normal block represented by the corresponding location field, and the second sub-field of the corresponding location field may have been a pointer information indicating another normal block in another victim super memory block replacing another bad block in the bad super memory block represented by the corresponding location field.

In response to a request of access to at least one of the bad super memory blocks, the controller may provide the normal blocks replacing the bad blocks in the access-requested bad super memory blocks by: searching the address value of the access-requested bad super memory block on an entry-by-entry basis in the bad group table; identifying a first normal block replacing a first one of the bad blocks in the respective access-requested bad super memory blocks through the physical location of the first normal block indicated by the location field having the address value of the respective access-requested bad super memory blocks in the first sub-field thereof; and identifying respective second and following normal blocks replacing respective second and following ones of the bad blocks in the respective access-requested bad super memory blocks through the physical

locations of the respective second and following normal blocks indicated by the location fields corresponding to the respective second and following normal blocks and having the address value of the respective access-requested bad super memory blocks in the first sub-fields of the location fields corresponding to the respective second and following normal blocks via the pointer information in the second sub-fields of the location fields corresponding to the respective first and following normal blocks.

In an embodiment, a method for operating a memory system which includes a memory device including a plurality of super memory blocks each having a plurality of memory blocks, the method may include: detecting two or more bad super memory blocks each including at least one bad block among the super memory blocks; selecting at least one victim super memory block among the bad super memory blocks; and replacing the bad blocks in each remaining bad super memory block with normal blocks of the victim super memory block, the replacing may include generating a bad group table indicating a mapping relationship between the bad blocks of the remaining bad super memory blocks and the corresponding normal blocks, which replaces the respective bad blocks, of the at least one victim super memory block.

The replacing may include, in response to a request of access to one or more of the bad super memory blocks, providing access to the normal blocks replacing the bad blocks in the access-requested bad super memory blocks according to the mapping relationship.

The respective bad blocks may be replaced with the respective normal blocks having the same physical locations as the respective bad blocks in the respective bad super memory blocks, and the physical location may be of a plane level in the memory device.

The bad group table may include at least one entry respectively representing the at least one victim super memory block, the at least one entry including a plurality of location fields respectively representing physical locations of memory blocks of the at least one victim super memory block, each location field representing the normal block in the at least one victim super memory block having an address value of the bad super memory block having the bad block, which is replaced by the normal block represented thereby.

The bad group table may include at least one row and a plurality of columns configured in the form of a matrix, the at least one victim super memory block corresponds to one row, memory blocks included in the at least one victim super memory block correspond to the columns, and the bad blocks included in the bad super memory blocks are mapped to the columns.

The providing of access may include: searching the address values of the access-requested bad super memory blocks on an entry-by-entry basis in the bad group table; and identifying the normal blocks replacing the bad blocks in the access-requested bad super memory blocks through the physical locations of the normal blocks indicated by the location fields having the address values of the access-requested bad super memory blocks.

The bad group table may include at least one entry respectively representing the at least one victim super memory block, for the at least one entry, the bad group table may include a plurality of location fields respectively representing physical locations of memory blocks of the at least one victim super memory block and each including first and second sub-fields, the first sub-field, a corresponding location field of which represents the normal block in the at least

one victim super memory block, may have been an address value of the bad super memory block having the bad block, which is replaced by the normal block represented by the corresponding location field, and the second sub-field of the corresponding location field may have been a pointer information indicating another normal block in another victim super memory block replacing another bad block in the bad super memory block represented by the corresponding location field.

The providing of access may include: searching the address value of the access-requested bad super memory blocks on an entry-by-entry basis in the bad group table; identifying a first normal block replacing a first one of the bad blocks in the respective access-requested bad super memory blocks through the physical location of the first normal block indicated by the location field having the address value of the respective access-requested bad super memory blocks in the first sub-field thereof; and identifying respective second and following normal blocks replacing respective second and following ones of the bad blocks in the respective access-requested bad super memory blocks through the physical locations of the respective second and following normal blocks indicated by the location fields corresponding to the respective second and following normal blocks and having the address value of the respective access-requested bad super memory blocks in the first sub-fields of the location fields corresponding to the respective second and following normal blocks via the pointer information in the second sub-fields of the location fields corresponding to the respective first and following normal blocks.

In an embodiment, a memory system may include: a memory device including a plurality of dies, each die comprising a plurality of planes and each plane comprising a plurality of memory blocks; a controller suitable for arranging the plurality of memory blocks in a plurality of super memory blocks, detecting two or more bad super memory blocks each including a bad block, selecting a victim super memory block among the bad super memory blocks, and generating a bad group table indicating a mapping relationship between the bad block of each of the remaining bad super memory blocks and the corresponding normal blocks of the victim super memory block for replacing the bad block of each of the remaining bad super memory blocks with the corresponding normal blocks of the victim super memory block.

In response to a request of access to a bad super memory block, the controller may provide access to the normal blocks replacing the bad blocks in the access-requested bad super memory blocks according to the mapping relationship.

The controller may replace the bad blocks with the normal blocks having the same physical locations as the bad blocks in the bad super memory blocks, and the physical location may be of a plane level in the memory device.

BRIEF DESCRIPTION OF THE DRAWINGS

These and other features and advantages of the present invention will become apparent to those skilled in the art to which the present invention pertains from the following detailed description in reference to the accompanying drawings, wherein:

FIG. 1 is a block diagram illustrating a data processing system including a memory system in accordance with an embodiment of the present invention;

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FIG. 2 is a schematic diagram illustrating an exemplary configuration of a memory device employed in the memory system of FIG. 1;

FIG. 3 is a circuit diagram illustrating an exemplary configuration of a memory cell array of a memory block in the memory device of FIG. 2;

FIG. 4 is a schematic diagram illustrating an exemplary three-dimensional structure of the memory device of FIG. 2;

FIG. 5A is an exemplary diagram illustrating a super memory block;

FIG. 5B is a diagram illustrating an operation of managing memory blocks in units of super memory blocks in the memory system in accordance with an embodiment of the present invention;

FIG. 6 is a flow chart illustrating a method for operating a memory system in accordance with an embodiment.

FIG. 7 is a flow chart illustrating an operation of allocating a normal block of a victim super memory block in accordance with an embodiment.

FIGS. 8A and 8B are diagrams illustrating the operation of allocating a normal block of a victim super memory block in accordance with an embodiment.

FIG. 9 is a flow chart illustrating an operation of allocating a normal block of a victim super memory block in accordance with an embodiment.

FIGS. 10A and 10B are diagrams illustrating an operation of allocating a normal block of a victim super memory block in accordance with an embodiment.

FIG. 11 is a flow chart illustrating an operation of deducing a normal block of a victim super memory block in accordance with an embodiment.

FIG. 12 is a flow chart illustrating an operation of deducing a normal block of a victim super memory block in accordance with another embodiment.

FIGS. 13 to 18 are diagrams schematically illustrating application examples of the data processing system of FIG. 1 in accordance with various embodiments of the present invention.

DETAILED DESCRIPTION

Various embodiments of the present invention are described below in more detail with reference to the accompanying drawings. We note, however, that the present invention may be embodied in different other embodiments, forms and variations thereof and should not be construed as being limited to the embodiments set forth herein. Rather, the described embodiments are provided so that this disclosure will be thorough and complete, and will fully convey the present invention to those skilled in the art to which this invention pertains. Throughout the disclosure, like reference numerals refer to like parts throughout the various figures and embodiments of the present invention.

It will be understood that, although the terms “first”, “second”, “third”, and so on may be used herein to describe various elements, these elements are not limited by these terms. These terms are used to distinguish one element from another element. Thus, a first element described below could also be termed as a second or third element without departing from the spirit and scope of the present invention.

The drawings are not necessarily to scale and, in some instances, proportions may have been exaggerated in order to clearly illustrate features of the embodiments.

It will be further understood that when an element is referred to as being “connected to”, or “coupled to” another element, it may be directly on, connected to, or coupled to the other element, or one or more intervening elements may

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be present. In addition, it will also be understood that when an element is referred to as being “between” two elements, it may be the only element between the two elements, or one or more intervening elements may also be present.

The terminology used herein is for the purpose of describing particular embodiments only and is not intended to be limiting of the present invention. As used herein, singular forms are intended to include the plural forms as well, unless the context clearly indicates otherwise. It will be further understood that the terms “comprises,” “comprising,” “includes,” and “including” when used in this specification, specify the presence of the stated elements and do not preclude the presence or addition of one or more other elements. As used herein, the term “and/or” includes any and all combinations of one or more of the associated listed items.

Unless otherwise defined, all terms including technical and scientific terms used herein have the same meaning as commonly understood by one of ordinary skill in the art to which the present invention belongs in view of the present disclosure. It will be further understood that terms, such as those defined in commonly used dictionaries, should be interpreted as having a meaning that is consistent with their meaning in the context of the present disclosure and the relevant art and will not be interpreted in an idealized or overly formal sense unless expressly so defined herein.

In the following description, numerous specific details are set forth in order to provide a thorough understanding of the present invention. The present invention may be practiced without some or all of these specific details. In other instances, well-known process structures and/or processes have not been described in detail in order not to unnecessarily obscure the present invention.

It is also noted, that in some instances, as would be apparent to those skilled in the relevant art, a feature or element described in connection with one embodiment may be used singly or in combination with other features or elements of an embodiment, unless otherwise specifically indicated.

Hereinafter, the various embodiments of the present invention will be described in detail with reference to the attached drawings.

FIG. 1 is a block diagram illustrating a data processing system 100 including a memory system 110 in accordance with an embodiment of the present invention.

Referring to FIG. 1, the data processing system 100 may include a host 102 and the memory system 110.

The host 102 may include portable electronic devices such as a mobile phone, MP3 player and laptop computer or non-portable electronic devices such as a desktop computer, game machine, TV and projector.

The host 102 may include at least one OS (operating system) for managing and controlling the overall functions and operations of the host 102, and provide an operation between the host 102 and a user using the data processing system 100 or the memory system 110. The OS may support functions and operations corresponding to the use purpose and usage of a user. For example, the OS may be divided into a general OS and a mobile OS, depending on the mobility of the host 102. The general OS may be divided into a personal OS and an enterprise OS, depending on the environment of a user. For example, the personal OS configured to support a function of providing a service to general users may include Windows and Chrome, and the enterprise OS configured to secure and support high performance may include Windows server, Linux and Unix.

Furthermore, the mobile OS configured to support a function of providing a mobile service to users and a power saving function of a system may include Android, iOS and Windows Mobile. The host **102** may include a plurality of OSs, and execute an OS to perform an operation corresponding to a user's request on the memory system **110**.

The memory system **110** may operate to store data for the host **102** in response to a request of the host **102**. Non-limited examples of the memory system **110** may include a solid state drive (SSD), a multi-media card (MMC), a secure digital (SD) card, a universal storage bus (USB) device, a universal flash storage (UFS) device, compact flash (CF) card, a smart media card (SMC), a personal computer memory card international association (PCMCIA) card and memory stick. The MMC may include an embedded MMC (eMMC), reduced size MMC (RS-MMC) and micro-MMC. The SD card may include a mini-SD card and micro-SD card.

The memory system **110** may be embodied by various types of storage devices. Non-limited examples of storage devices included in the memory system **110** may include volatile memory devices such as a DRAM dynamic random access memory (DRAM) and a static RAM (SRAM) and nonvolatile memory devices such as a read only memory (ROM), a mask ROM (MROM), a programmable ROM (PROM), an erasable programmable ROM (EPROM), an electrically erasable programmable ROM (EEPROM), a ferroelectric RAM (FRAM), a phase-change RAM (PRAM), a magneto-resistive RAM (MRAM), resistive RAM (RRAM) and a flash memory. The flash memory may have a 3-dimensional (3D) stack structure.

The memory system **110** may include a memory device **150** and a controller **130**. The memory device **150** may store data for the host **102**, and the controller **130** may control data storage into the memory device **150**.

The controller **130** and the memory device **150** may be integrated into a single semiconductor device, which may be included in the various types of memory systems as exemplified above.

Non-limited application examples of the memory system **110** may include a computer, an Ultra Mobile PC (UMPC), a workstation, a net-book, a Personal Digital Assistant (PDA), a portable computer, a web tablet, a tablet computer, a wireless phone, a mobile phone, a smart phone, an e-book, a Portable Multimedia Player (PMP), a portable game machine, a navigation system, a black box, a digital camera, a Digital Multimedia Broadcasting (DMB) player, a 3-dimensional television, a smart television, a digital audio recorder, a digital audio player, a digital picture recorder, a digital picture player, a digital video recorder, a digital video player, a storage device constituting a data center, a device capable of transmitting/receiving information in a wireless environment, one of various electronic devices constituting a home network, one of various electronic devices constituting a computer network, one of various electronic devices constituting a telematics network, a Radio Frequency Identification (RFID) device, or one of various components constituting a computing system.

The memory device **150** may be a nonvolatile memory device and may retain data stored therein even though power is not supplied. The memory device **150** may store data provided from the host **102** through a write operation, and provide data stored therein to the host **102** through a read operation. The memory device **150** may include a plurality of memory dies (not shown), each memory die including a plurality of planes (not shown), each plane including a plurality of memory blocks **152** to **156**, each of the memory

blocks **152** to **156** may include a plurality of pages, and each of the pages may include a plurality of memory cells coupled to a word line.

The controller **130** may control the memory device **150** in response to a request from the host **102**. For example, the controller **130** may provide data read from the memory device **150** to the host **102**, and store data provided from the host **102** into the memory device **150**. For this operation, the controller **130** may control read, write, program and erase operations of the memory device **150**.

The controller **130** may include a host interface (I/F) unit **132**, a processor **134**, an error correction code (ECC) unit **138**, a Power Management Unit (PMU) **140**, a NAND flash controller (NFC) **142** and a memory **144** all operatively coupled via an internal bus.

The host interface unit **132** may be configured to process a command and data of the host **102**, and may communicate with the host **102** through one or more of various interface protocols such as universal serial bus (USB), multi-media card (MMC), peripheral component interconnect-express (PCI-E), small computer system interface (SCSI), serial-attached SCSI (SAS), serial advanced technology attachment (SATA), parallel advanced technology attachment (PATA), enhanced small disk interface (ESDI) and integrated drive electronics (IDE).

The ECC unit **138** may detect and correct an error contained in the data read from the memory device **150**. In other words, the ECC unit **138** may perform an error correction decoding process to the data read from the memory device **150** through an ECC code used during an ECC encoding process. According to a result of the error correction decoding process, the ECC unit **138** may output a signal, for example, an error correction success/fail signal. When the number of error bits is more than a threshold value of correctable error bits, the ECC unit **138** may not correct the error bits, and may output an error correction fail signal.

The ECC unit **138** may perform error correction through a coded modulation such as Low Density Parity Check (LDPC) code, Bose-Chaudhri-Hocquenghem (BCH) code, turbo code, Reed-Solomon code, convolution code, Recursive Systematic Code (RSC), Trellis-Coded Modulation (TCM) and Block coded modulation (BCM). However, the ECC unit **138** is not limited thereto. The ECC unit **138** may include all circuits, modules, systems or devices for error correction.

The PMU **140** may provide and manage power of the controller **130**.

The NFC **142** may serve as a memory/storage interface for interfacing the controller **130** and the memory device **150** such that the controller **130** controls the memory device **150** in response to a request from the host **102**. When the memory device **150** is a flash memory or specifically a NAND flash memory, the NFC **142** may generate a control signal for the memory device **150** and process data to be provided to the memory device **150** under the control of the processor **134**. The NFC **142** may work as an interface (e.g., a NAND flash interface) for processing a command and data between the controller **130** and the memory device **150**. Specifically, the NFC **142** may support data transfer between the controller **130** and the memory device **150**.

The memory **144** may serve as a working memory of the memory system **110** and the controller **130**, and store data for driving the memory system **110** and the controller **130**. The controller **130** may control the memory device **150** to perform read, write, program and erase operations in response to a request from the host **102**. The controller **130** may provide data read from the memory device **150** to the

host **102**, may store data provided from the host **102** into the memory device **150**. The memory **144** may store data required for the controller **130** and the memory device **150** to perform these operations.

The memory **144** may be embodied by a volatile memory. For example, the memory **144** may be embodied by static random access memory (SRAM) or dynamic random access memory (DRAM). The memory **144** may be disposed within or out of the controller **130**. FIG. **1** exemplifies the memory **144** disposed within the controller **130**. In an embodiment, the memory **144** may be embodied by an external volatile memory having a memory interface transferring data between the memory **144** and the controller **130**.

The processor **134** may control the overall operations of the memory system **110**. The processor **134** may drive firmware to control the overall operations of the memory system **110**. The firmware may be referred to as flash translation layer (FTL).

The processor **134** of the controller **130** may include a management unit (not illustrated) for performing a bad management operation of the memory device **150**. The management unit may perform a bad block management operation of checking a bad block, in which a program fail occurs due to the characteristic of a NAND flash memory during a program operation, among the plurality of memory blocks **152** to **156** included in the memory device **150**. The management unit may write the program-failed data of the bad block to a new memory block. In the memory device **150** having a 3D stack structure, the bad block management operation may reduce the use efficiency of the memory device **150** and the reliability of the memory system **110**. Thus, the bad block management operation needs to be performed with more reliability.

FIG. **2** is a schematic diagram illustrating the memory device **150**.

Referring to FIG. **2**, the memory device **150** may include a plurality of memory blocks **0** to **N-1**, and each of the blocks **0** to **N-1** may include a plurality of pages, for example, 2^M pages, the number of which may vary according to circuit design. Memory cells included in the respective memory blocks **0** to **N-1** may be one or more of a single level cell (SLC) storing 1-bit data, a multi-level cell (MLC) storing 2-bit data, an MLC storing 3-bit data also referred to as a triple level cell (TLC), an MLC storing 4-bit level cell also referred to as a quadruple level cell (QLC), or an MLC storing 5-or-more-bit data.

FIG. **3** is a circuit diagram illustrating an exemplary configuration of a memory cell array of a memory block in the memory device **150**.

Referring to FIG. **3**, a memory block **330** which may correspond to any of the plurality of memory blocks **152** to **156** included in the memory device **150** of the memory system **110** may include a plurality of cell strings **340** coupled to a plurality of corresponding bit lines **BL0** to **BLm-1**. The cell string **340** of each column may include one or more drain select transistors **DST** and one or more source select transistors **SST**. Between the drain and source select transistors **DST** and **SST**, a plurality of memory cells **MC0** to **MCn-1** may be coupled in series. In an embodiment, each of the memory cell transistors **MC0** to **MCn-1** may be embodied by an MLC capable of storing data information of a plurality of bits. Each of the cell strings **340** may be electrically coupled to a corresponding bit line among the plurality of bit lines **BL0** to **BLm-1**. For example, as illustrated in FIG. **3**, the first cell string is coupled to the first bit line **BL0**, and the last cell string is coupled to the last bit line **BLm-1**.

Although FIG. **3** illustrates NAND flash memory cells, the invention is not limited in this way. It is noted that the memory cells may be NOR flash memory cells, or hybrid flash memory cells including two or more kinds of memory cells combined therein. Also, it is noted that the memory device **150** may be a flash memory device including a conductive floating gate as a charge storage layer or a charge trap flash (CTF) memory device including an insulation layer as a charge storage layer.

The memory device **150** may further include a voltage supply unit **310** which provides word line voltages including a program voltage, a read voltage and a pass voltage to supply to the word lines according to an operation mode. The voltage generation operation of the voltage supply unit **310** may be controlled by a control circuit (not illustrated). Under the control of the control circuit, the voltage supply unit **310** may select one of the memory blocks (or sectors) of the memory cell array, select one of the word lines of the selected memory block, and provide the word line voltages to the selected word line and the unselected word lines as may be needed.

The memory device **150** may include a read/write circuit **320** which is controlled by the control circuit. During a verification/normal read operation, the read/write circuit **320** may operate as a sense amplifier for reading data from the memory cell array. During a program operation, the read/write circuit **320** may operate as a write driver for driving bit lines according to data to be stored in the memory cell array. During a program operation, the read/write circuit **320** may receive from a buffer (not illustrated) data to be stored into the memory cell array, and drive bit lines according to the received data. The read/write circuit **320** may include a plurality of page buffers **322** to **326** respectively corresponding to columns (or bit lines) or column pairs (or bit line pairs), and each of the page buffers **322** to **326** may include a plurality of latches (not illustrated).

FIG. **4** is a schematic diagram illustrating an exemplary 3D structure of the memory device **150**.

The memory device **150** may be embodied by a 2D or 3D memory device. Specifically, as illustrated in FIG. **4**, the memory device **150** may be embodied by a nonvolatile memory device having a 3D stack structure. When the memory device **150** has a 3D structure, the memory device **150** may include a plurality of memory blocks **BLK0** to **BLKN-1** each having a 3D structure (or vertical structure).

FIG. **5A** is an exemplary diagram illustrating a super memory block.

Referring to FIG. **5A**, the memory device **150** includes a plurality of memory blocks **BLOCK000** to **BLOCK11N**.

The memory device **150** includes a zeroth memory die **DIE0** coupled to a zeroth channel **CH0** and a first memory die **DIE1** coupled to a first channel **CH1**. The zeroth channel **CH0** and the first channel **CH1** may input/output data in an interleaving scheme.

The zeroth memory die **DIE0** includes a plurality of planes **PLANE00** and **PLANE01** respectively coupled to a plurality of ways **WAY0** and **WAY1** for transferring data in the interleaving scheme by sharing the zeroth channel **CH0**.

The first memory die **DIE1** includes a plurality of planes **PLANE10** and **PLANE11** respectively coupled to a plurality of ways **WAY2** and **WAY3** transferring data in the interleaving scheme by sharing the first channel **CH1**.

The first plane **PLANE00** of the zeroth memory die **DIE0** includes a predetermined number of memory blocks **BLOCK000** to **BLOCK00N** among the plurality of memory blocks **BLOCK000** to **BLOCK11N**.

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The second plane PLANE01 of the zeroth memory die DIE0 includes the predetermined number of memory blocks BLOCK010 to BLOCK01N among the plurality of memory blocks BLOCK000 to BLOCK11N.

The first plane PLANE10 of the first memory die DIE1 includes the predetermined number of memory blocks BLOCK100 to BLOCK10N among the plurality of memory blocks BLOCK000 to BLOCK11N.

The second plane PLANE11 of the first memory die DIE1 includes the predetermined number of memory blocks BLOCK110 to BLOCK11N among the plurality of memory blocks BLOCK000 to BLOCK11N.

In this manner, the plurality of memory blocks BLOCK000 to BLOCK11N included in the memory device 150 may be divided according to their physical locations for receiving and providing data through the same ways or the same channels.

FIG. 5A illustrates, as an example, two memory dies DIE0 and DIE1 included in the memory device 150, two planes included in each of the dies DIE0 and DIE1 and the same predetermined number of memory blocks included in each of planes. It is noted that, according to a designer's choice, the number of memory dies may be greater or smaller than two. Also, the number of planes may be greater or smaller than two and the number of memory blocks included in each plane may be adjusted variously according to a designer's choice.

Meanwhile, the controller 130 may manage a plurality of memory blocks by grouping the memory blocks into several super memory blocks, each of which the controller 130 may select simultaneously. For example, the controller 130 may use a scheme of dividing a plurality of memory blocks according to simultaneous selection and operation of memory blocks. For example, the controller 130 may manage a plurality of memory blocks which are divided into different dies or different planes through a dividing scheme according to physical positions, by grouping memory blocks capable of being selected simultaneously among the plurality of memory blocks and thereby dividing the plurality of memory blocks into super memory blocks.

The scheme of grouping, in this manner, the plurality of memory blocks into super memory blocks by the controller 130 may be modified according to a designer's choice. Three exemplary schemes will be exemplified herein.

According to a first example, a method for managing the memory blocks of the memory device 150 into super memory blocks may include to manage one super memory block A1 by grouping, by the controller 130, one optional memory block BLOCK000 in the first plane PLANE00 and one optional memory block BLOCK010 in the second plane PLANE01 of the zeroth memory die DIE0 between the plurality of memory dies DIE0 and DIE1 included in the memory device 150. When applying the first scheme to the first memory die DIE1 between the plurality of memory dies DIE0 and DIE1 included in the memory device 150, the controller 130 may manage one super memory block A2 by grouping one optional memory block BLOCK100 in the first plane PLANE10 and one optional memory block BLOCK110 in the second plane PLANE11 of the first memory die DIE1.

Another example, may include to manage one super memory block B1 by grouping, by the controller 130, one optional memory block BLOCK002 included in the first plane PLANE00 of the zeroth memory die DIE0 between the plurality of memory dies DIE0 and DIE1 included in the memory device 150 and one optional memory block BLOCK102 included in the first plane PLANE10 of the first

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memory die DIE1. When applying the second scheme again, the controller 130 may manage one super memory block B2 by grouping one optional memory block BLOCK012 included in the second plane PLANE01 of the zeroth memory die DIE0 between the plurality of memory dies DIE0 and DIE1 included in the memory device 150 and one optional memory block BLOCK112 included in the second plane PLANE11 of the first memory die DIE1.

A third example may include to manage one super memory block C by grouping, by the controller 130, one optional memory block BLOCK001 included in the first plane PLANE00 of the zeroth memory die DIE0 between the plurality of memory dies DIE0 and DIE1 included in the memory device 150, one optional memory block BLOCK011 included in the second plane PLANE01 of the zeroth memory die DIE0, one optional memory block BLOCK101 included in the first plane PLANE10 of the first memory die DIE1 and one optional memory block BLOCK111 included in the second plane PLANE11 of the first memory die DIE1.

In the respective super memory blocks, memory blocks may be simultaneously selected through an interleaving scheme, for example, a channel interleaving scheme, a memory die interleaving scheme, a memory chip interleaving scheme or a way interleaving scheme.

FIG. 5B is a diagram illustrating an operation of managing memory blocks in units of super memory blocks in the memory system in accordance with an embodiment of the present invention.

First, it is exemplified that the memory device 150 includes eight memory dies DIE<0:7>, each of the eight memory dies DIE<0:7> includes four planes PLANE<0:3> to allow the eight memory dies DIE<0:7> to include total 32 planes PLANE<0:3>*8, and each of the 32 planes PLANE<0:3>*8 includes 1,024 memory blocks BLOCK<0:1023>. In other words, it is exemplified that the memory device 150 includes total 32,768 memory blocks BLOCK<0:1023>*32.

Also, it is exemplified that, in the memory device 150, the total 32 planes PLANE<0:3>*8 included in the eight memory dies DIE<0:7> input/output data through two channels CH<0:1> and eight ways WAY<0:7>. Namely, it is exemplified that, in the memory device 150, four planes PLANE<0:3> of the respective 8 dies DIE<0:7> share one of 8 ways WAY<0:7>. Also, a first half of the 8 ways WAY<0:7> (e.g., first four ways WAY<0:3>) share a first channel CH0 and a second half of the 8 ways WAY<0:7> (e.g., last four ways WAY<4:7>) share a second channel CH1.

The controller 130 of the memory system 110 in accordance with an embodiment of the present invention uses a scheme of managing the plurality of memory blocks included in the memory device 150, by dividing them in units of super memory blocks.

As exemplified in FIG. 5B, the controller 130 manages each of the super memory blocks SUPER BLOCK<0:1023> by selecting one arbitrary memory block in each of 32 planes PLANE<0:3>*8 included in the memory device 150. Therefore, 32 memory blocks are included in each of the super memory blocks SUPER BLOCK<0:1023>.

Since the controller 130 selects simultaneously the 32 memory blocks included in each of the super memory blocks SUPER BLOCK<0:1023>, in a configuration in which management is performed in units of super memory blocks as in FIG. 6, only super memory block addresses are used for selecting the respective super memory blocks SUPER BLOCK<0:1023>.

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In other words, in a configuration in which management is performed in units of super memory blocks, instead of using memory block addresses (not shown) for selecting the respective 32,768 memory blocks BLOCK<0:1023>*32 included in the memory device **150**, only super memory block addresses (not shown) are used for selecting the respective 1,024 super memory blocks SUPER BLOCK<0:1023>.

In this manner, in order to use only the super memory block addresses, the controller **130** uses a scheme of managing super memory blocks by grouping memory blocks of the same locations in the respective 32 planes PLANE<0:3>*8 included in the memory device **150**.

For example, the controller **130** manages a zeroth super memory block SUPER BLOCK**0** by grouping 32 zeroth memory blocks BLOCK**0** in the respective 32 planes PLANE<0:3>*8 included in the memory device **150**, manages a first super memory block SUPER BLOCK**1** by grouping 32 first memory blocks BLOCK**1** in the respective 32 planes PLANE<0:3>*8, and manages a second super memory block SUPER BLOCK**2** by grouping 32 second memory blocks BLOCK**2** in the respective 32 planes PLANE<0:3>*8. In this manner, the controller **130** manages the 32,768 memory blocks BLOCK<0:1023>*32 included in the memory device **150**, by dividing them into a total of 1,024 super memory blocks SUPER BLOCK<0:1023>.

Meanwhile, it is substantially impossible for all the memory blocks included in the memory device **150**, to operate normally. Namely, it is the norm that bad memory blocks which do not operate normally exist to some extent among the plurality of memory blocks included in the memory device **150**. For example, in the embodiment of FIG. **5B**, where it is illustrated that 32,768 memory blocks BLOCK<0:1023>*32 are included in the memory device **150**, about 650 memory blocks corresponding to approximately 2% may be bad memory blocks.

In this regard, as described above, in the case where the controller **130** uses the scheme of managing super memory blocks by grouping memory blocks of the same locations in the respective 32 planes PLANE<0:3>*8 included in the memory device **150** in order to use only super memory block addresses, a bad super memory block, in which a bad memory block is included among the super memory blocks SUPER BLOCK<0:1023>, may not operate normally. That is to say, if even one memory block among the 32 memory blocks included in each of the super memory blocks SUPER BLOCK<0:1023> is determined as a bad memory block, a corresponding bad super memory block may not operate normally.

In this manner, even though only one memory block is a bad memory block and all the remaining 31 memory blocks are normal among the 32 memory blocks included in a super memory block, then the super memory block is a bad super memory block and cannot be used, which is markedly inefficient.

In consideration of this fact, in the memory system **110** in accordance with an embodiment of the present invention, a bad super memory block where at least one bad memory block is included is reused through methods of operating the memory system **110**, which is to be described below with reference to FIGS. **6** to **12**.

FIG. **6** is a flow chart illustrating a method of operating the memory system **110** in accordance with an embodiment.

Referring to FIG. **6**, the controller **130** may detect at least one bad block in the memory device **150** at step **611**.

In detail, among a plurality of super memory blocks, the controller **130** may detect a super memory block in which at

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least one bad block is included as a bad super memory block. Also, the controller **130** may select at least one victim super memory block among a plurality of the bad super memory blocks at step **612**. For example, based on a number of bad blocks included in the respective bad super memory blocks, the controller **130** may select a bad super memory block having smallest number of bad blocks as a victim super memory block among the bad super memory blocks. The controller **130** may detect the locations of bad blocks included in the respective bad super memory blocks and store the locations of the bad blocks in a bad block summary table.

At step **613**, the controller **130** may allocate the normal blocks included in the victim super memory block in replacement of the bad blocks included in the remaining bad super memory blocks.

The controller **130** may manage mapping information representing mapping physical-location-relationship between the respective normal blocks of the victim super memory block and the respective bad blocks of the remaining bad super memory blocks. That is to say, the controller **130** may respectively map the normal blocks of the victim super memory block to the bad blocks of the remaining bad super memory blocks. The controller **130** may store the mapping information in a bad group table. The bad group table may include one or more entries respectively corresponding to a plurality of the victim super memory blocks. For example, when assuming that a maximum of 20 super memory blocks are selected as victim super memory blocks, the bad group table may have 20 entries.

FIG. **7** is a flow chart illustrating an operation at step **613** in accordance with an embodiment. FIGS. **8A** and **8B** are diagrams illustrating the operation at step **613** in accordance with an embodiment.

Referring to FIGS. **7** and **8A**, at step **711**, the controller **130** may select normal blocks of the victim super memory block for the bad blocks of the bad super memory block. The selected normal blocks may have the same physical locations as the bad blocks of the bad super memory block. The physical location may be of a plane level.

For example, a super memory block **145** ('SUPER BLOCK **145**') may be selected as a victim super memory block. It is assumed that the victim super memory block **145** ('SUPER BLOCK **145**') includes bad blocks **145** of plane **0** in die **0** and plane **0** in die **1**. For example, a super memory block **180** ('SUPER BLOCK **180**') may be a bad super memory block. It is assumed that the bad super memory block **180** ('SUPER BLOCK **180**') includes bad blocks **180** of planes **2** and **3** of die **0**.

At step **711**, the controller **130** may select normal blocks **145** of planes **2** and **3** of die **0** of the victim super memory block **145** ('SUPER BLOCK **145**'), which are the same physical location of the bad blocks **180** of the bad super memory block **180** ('SUPER BLOCK **180**'), for the bad blocks **180** of the bad super memory block **180** ('SUPER BLOCK **180**').

At step **713**, the controller **130** may map the selected normal blocks of the victim super memory block to the bad blocks of the bad super memory block.

The physical location information of the memory blocks of the victim super memory blocks and the mapping information between the victim super memory blocks and the remaining bad super memory blocks may be included in the bad group table shown in FIG. **8B**. Referring to FIG. **8B**, the bad group table may include one or more entries respectively representing the victim super memory blocks. FIG. **8B** exemplifies a plurality of entries respectively representing

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victim super memory blocks **145**, **504**, **607**, and so forth. For each entry, the bad group table may include a plurality of location fields respectively representing physical locations of memory blocks of the victim super memory block represented by the entry. The physical locations of the memory blocks may be of the plane level as exemplified in FIG. **8B**.

The controller **130** may mark the bad blocks of the victim super memory block with a predetermined value in the bad group table at step **711**. FIG. **8B** exemplifies the bad blocks, which are located in plane **0** of die **0** and plane **0** of die **1**, of the victim super memory block **145** marked with a value of "FFFF" in the bad group table.

Also, the controller **130** may map the selected normal blocks of the victim super memory block to the bad blocks of the bad super memory block at step **713**. The selected normal blocks and the bad blocks may have the same physical locations. As exemplified in FIG. **8B**, the controller **130** may select normal blocks, which are located in the planes **2** and **3** of die **0** in the victim super memory block **145**, for bad blocks of the same physical location in bad super memory block **180**. FIG. **8B** exemplifies the location fields representing the selected normal blocks of the planes **2** and **3** of die **0** in the victim super memory block **145**, which are marked with the address value "180" representing the bad super memory block **180** in the bad group table. In other words, the bad group table may be configured by one or more rows and a plurality of columns. A plurality of victim super memory blocks may correspond to a plurality of rows, respectively, and the memory blocks included in each victim super memory block may correspond to the plurality of columns, respectively. For example, the controller **130** may add super block addresses to map the normal blocks, that is, 'DIE **0**, PLANE **2**' and 'DIE **0**, PLANE **3**,' included in the victim super memory block, that is, 'SUPER BLOCK **145**,' to the bad super memory block, that is, 'SUPER BLOCK **180**,' in the bad group table. In detail, as shown in the drawing, after storing a super block address indicating 'SUPER BLOCK **145**' in the first row of the bad group table, a super block address indicating 'SUPER BLOCK **180**' is stored in each of a column corresponding to 'DIE **0**, PLANE **2**' and a column corresponding to 'DIE **0**, PLANE **3**' among a plurality of columns corresponding to the first row. While a value of 'FFFF' is stored in each of a column corresponding to 'DIE **0**, PLANE **0**' and a column corresponding to 'DIE **1**, PLANE **0**' among the plurality of columns corresponding to the first row of the bad group table, this is to represent that 'DIE **0**, PLANE **0**' and 'DIE **1**, PLANE **0**' of 'SUPER BLOCK **145**' corresponding to the first row of the bad group table are bad blocks.

While not shown in detail in FIG. **8A**, storage of a super block address indicating 'SUPER BLOCK **166**' in a column corresponding to 'DIE **0**, PLANE **1**' among the plurality of columns corresponding to the first row of the bad group table means that 'DIE **0**, PLANE **1**' of 'SUPER BLOCK **166**' is a bad block and 'DIE **0**, PLANE **1**' of 'SUPER BLOCK **145**' as a normal block is used by being mapped to replace the bad block. Similarly, storage of a super block address indicating 'SUPER BLOCK **501**' in a column corresponding to 'DIE **7**, PLANE **3**' among the plurality of columns corresponding to the first row of the bad group table means that 'DIE **7**, PLANE **3**' of 'SUPER BLOCK **501**' is a bad block and 'DIE **7**, PLANE **3**' of 'SUPER BLOCK **145**' as a normal block is used by being mapped to replace the bad block. Moreover, storage of a super block address indicating 'SUPER BLOCK **463**' in a column corresponding to 'DIE **7**, PLANE **3**' among a plurality of columns corresponding to the second row of the bad group table means that 'DIE **7**, PLANE **3**' of

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'SUPER BLOCK **463**' is a bad block and 'DIE **7**, PLANE **3**' of 'SUPER BLOCK **504**' as a normal block is used by being mapped to replace the bad block.

FIG. **9** is a flow chart illustrating an operation of at step **613** in accordance with another embodiment. FIGS. **10A** and **10B** are diagrams illustrating the operation at step **613** in accordance with an embodiment.

Referring to FIG. **9**, steps **911** and **913** may be the same as steps **711** and **713** described with reference to FIGS. **7**, **8A** and **8B**.

For example, super memory blocks **145** and **607** (respectively 'SUPER BLOCK **145**' and 'SUPER BLOCK **607**') may be selected as victim super memory blocks. It is assumed that the victim super memory block **145** ('SUPER BLOCK **145**') includes bad block **145** of plane **0** in a die **0** and plane **0** in a die **1**. It is also assumed that the victim super memory block **607** ('SUPER BLOCK **607**') includes bad block **607** of plane **3** in die **0**. It is further assumed that the bad super memory block **200** ('SUPER BLOCK **200**') includes bad blocks **200** of plane **3** of die **0** and plane **0** of die **1**. Therefore, by using only the normal blocks included in 'SUPER BLOCK **145**,' it is impossible to replace all the bad blocks of 'SUPER BLOCK **200**,' and similarly, by using only the normal blocks included in 'SUPER BLOCK **607**,' it is impossible to replace all the bad blocks of 'SUPER BLOCK **200**.' In this case, the controller **130** may select normal blocks from two or more victim super memory blocks for bad blocks of the single bad super memory block. For example, at steps **911** and **913**, the controller **130** may select and map normal block **145** of plane **3** of die **0** of the victim super memory block **145** ('SUPER BLOCK **145**'), which are the same physical location of the bad block **200** of the bad super memory block **200** ('SUPER BLOCK **200**'), to the bad block **200** of the bad super memory block **200** ('SUPER BLOCK **200**').

FIG. **10B** exemplifies a first sub-field of the location field representing the selected normal block **145** of the plane **3** of die **0** in the victim super memory block **145**, which are marked with the address value "200" representing the bad super memory block **200** in the bad group table. As described above, for each entry, the bad group table may include a plurality of location fields respectively representing physical locations of memory blocks of the victim super memory block represented by the entry. Differently from the embodiment of the bad group table described with reference to FIG. **8B**, each location field representing the selected normal blocks of the victim super memory block may include first and second sub-fields in the bad group table of FIG. **10B**. The first sub-field may have the mapping information between the victim super memory blocks and the remaining bad super memory blocks, which is the same as the embodiment of the bad group table described with reference to FIG. **8B**. The second sub-field will be described later.

At step **915**, the controller **130** may determine whether the bad super memory block still have one or more bad blocks which is not mapped to a first victim super memory block (e.g., the victim super memory block **145**) even after all the available normal blocks of the first victim super memory block are mapped to the bad blocks of the bad super memory block at step **913**. As exemplified in FIG. **10A**, the bad block **200** of plane **0** of die **1** in the bad super memory block **200** cannot be mapped to the available normal blocks **145** of the victim super memory block **145** since block **145** of plane **0** of die **1** in the victim super memory block **145** is a bad block. In this case, the controller **130** may determine the bad super memory block **200** to still have bad block **200** of plane **0** of

die 1 which is not mapped to the first victim super memory block 145 even after all the available normal blocks 145 of the first victim super memory block 145 are mapped to the bad blocks of the bad super memory block at step 913.

In the case where the controller 130 determines at step 915 the bad super memory block to still have one or more bad blocks not mapped to the first victim super memory block (YES), at step 917, the controller 130 may map a selected normal block of a second victim super memory block, for example, may map the selected normal block 607 of plane 0 of die 1 of the victim super memory block 607 ('SUPER BLOCK 607'), which is at the same physical location of the remaining bad block 200 of the bad super memory block 200 ('SUPER BLOCK 200'), to the remaining bad block 200 of the bad super memory block 200 ('SUPER BLOCK 200').

FIG. 10B exemplifies the first sub-field of the location field representing the selected normal block 607 of the plane 0 of die 1 in the second victim super memory block 607 marked with the address value "200" representing the bad super memory block 200 in the bad group table.

As described above, each location field representing the selected normal blocks of the victim super memory block may include first and second sub-fields in the bad group table of FIG. 10B. The second sub-field may have pointer information indicating another victim super memory block having the selected normal block mapped to the bad blocks of the bad super memory block indicated by the first sub-fields included in the same location field as the second sub-field.

FIG. 10B exemplifies, in the location field representing the selected normal block 145 of plane 3 of die 0 in the first victim super memory block 145, the second sub-field having the pointer information "S3D1P0" indicating the second victim super memory block 607 having the selected normal block 607 of plane 0 of die 1 mapped to the bad block 200 of the bad super memory block 200 indicated by the first sub-fields included in the same location field as the second sub-field (i.e., the location field representing the selected normal block 145 of plane 3 of die 0 in the first victim super memory block 145).

Also, FIG. 10B exemplifies, in the location field representing the second selected normal block 607 of plane 0 of die 1 in the victim super memory block 607, the second sub-field having the pointer information "END" representing that there is no other victim super memory block for bad block in the bad super memory block 200 indicated by the first sub-fields included in the same location field as the second sub-field (i.e., the location field representing the selected normal block 607 of plane 0 of die 1 in the second victim super memory block 607) because all the bad block in the bad super memory block 200 are mapped to the selected normal blocks of the first and second victim super memory blocks 145 and 607. For example, when a bad block 200 of plane 0 of die 1 in a bad super memory block 200 is mapped to a normal block 607 of plane 0 of die 1 represented by a particular location field representing the physical location of plane 0 of die 1 through the first sub-field included therein and the second sub-field included therein has the pointer information "END", the bad block of plane 0 of die 1 may be the last one in the bad super memory block 200.

Further, FIG. 10B exemplifies, in the location field representing the bad block 145 of plane 0 of die 0 in the first victim super memory block 145, the second sub-field having the pointer information "VOID" representing void value because the first sub-fields included in the same location field (i.e., the location field representing the bad block 145

of plane 0 of die 0 in the first victim super memory block 145) has the value "FFFF" representing the bad block 145.

Referring back to FIG. 9, the controller 130 may further set values (e.g., the values of "S3D1P0", "END" and "VOID") of the second sub-fields of a plurality of entries respectively corresponding to a plurality of the victim super memory blocks (e.g., the first and second victim super memory blocks 145 and 607) having the normal blocks mapped to the bad blocks of the single bad super memory block (e.g., the bad super memory block 200) at step 917.

While not shown in detail in FIG. 8A, storage of a super block address indicating 'SUPER BLOCK 166' in a column corresponding to 'DIE 0, PLANE 1' among the plurality of columns corresponding to the first row of the bad group table means that 'DIE 0, PLANE 1' of 'SUPER BLOCK 166' is a bad block and 'DIE 0, PLANE 1' of 'SUPER BLOCK 145' as a normal block is used by being mapped to replace the bad block. Similarly, storage of a super block address indicating 'SUPER BLOCK 501' in a column corresponding to 'DIE 7, PLANE 3' among the plurality of columns corresponding to the first row of the bad group table means that 'DIE 7, PLANE 3' of 'SUPER BLOCK 501' is a bad block and 'DIE 7, PLANE 3' of 'SUPER BLOCK 145' as a normal block is used by being mapped to replace the bad block. Moreover, storage of a super block address indicating 'SUPER BLOCK 463' in a column corresponding to 'DIE 7, PLANE 3' among a plurality of columns corresponding to the second row of the bad group table means that 'DIE 7, PLANE 3' of 'SUPER BLOCK 463' is a bad block and 'DIE 7, PLANE 3' of 'SUPER BLOCK 504' as a normal block is used by being mapped to replace the bad block.

The controller 130 may map the normal block included in the victim super memory block, to the bad block included in the bad super memory block, by using the bad group table as shown in FIG. 8B. That is to say, as described above with reference to FIG. 8B, by using two rows in the bad group table, it is possible to cause the normal blocks included in the first and second victim super memory blocks to replace the bad blocks included in one bad super memory block. However, if the operation method as shown in FIG. 8B is used, when accessing the back super block, it is necessary to search two rows which are separated from each other, in the bad group table, and thus, a lengthy period may be required for searching.

Therefore, in an embodiment of the present disclosure, by generating a bad group table according to the scheme as shown in FIG. 10B, quick searching may become possible even when searching at least two rows which are separated from each other.

In detail, referring to FIG. 10B, the bad group table is configured by a plurality of rows and a plurality of columns, and each of the plurality of columns may include two regions, that is, a first region and a second region. A plurality of victim super memory blocks may correspond to the plurality of rows, respectively, memory blocks included in the victim super memory blocks may correspond to the respective first regions of the plurality of columns, and coupling information is stored in the respective second regions of the plurality of columns. The coupling information is information for allowing a corresponding column to find and be coupled to not a victim super memory block of a corresponding row but another victim super memory block. For example, the controller 130 may add a super block address to the first region of a normal block, that is, 'DIE 0, PLANE 3,' included in the first victim super memory block, that is, 'SUPER BLOCK 145,' to map the normal block, that is, 'DIE 0, PLANE 3,' to the bad super

memory block, that is, 'SUPER BLOCK 200,' in the bad group table. Also, the controller 130 may add a super block address to the first region of a normal block, that is, 'DIE 1, PLANE 0,' included in the second victim super memory block, that is, 'SUPER BLOCK 607,' to map the normal block, that is, 'DIE 1, PLANE 0,' to the bad super memory block, that is, 'SUPER BLOCK 200,' in the bad group table.

In detail, as shown in the drawing, after storing a super block address indicating 'SUPER BLOCK 145' in the first row of the bad group table, a super block address indicating 'SUPER BLOCK 200' is stored in the first region of a column corresponding to 'DIE 0, PLANE 3' among the plurality of columns corresponding to the first row. Similarly, after storing a super block address indicating 'SUPER BLOCK 607' in the third row of the bad group table, a super block address indicating 'SUPER BLOCK 200' is stored in the first region of a column corresponding to 'DIE 1, PLANE 0' among the plurality of columns corresponding to the third row. Then, information 3SD0P1 for finding the column corresponding to 'DIE 1, PLANE 0' among the plurality of columns corresponding to the third row of the bad group table is stored in the second region of the column corresponding to 'DIE 0, PLANE 3' among the plurality of columns corresponding to the first row of the bad group table. Through this, in order to access 'SUPER BLOCK 200,' after confirming, by searching the respective first regions of the plurality of columns corresponding to the first row of the bad group table, that a normal block for replacing the bad block positioned in 'DIE 0, PLANE 3' of 'SUPER BLOCK 200' is included in 'SUPER BLOCK 145,' it is possible to immediately find the first region of the column corresponding to 'DIE 1, PLANE 0' of the third row, through the second region of the column corresponding to 'DIE 0, PLANE 3' of 'SUPER BLOCK 145.' Since the third row corresponds to 'SUPER BLOCK 607,' it may be confirmed that a normal block for replacing the bad block positioned in 'DIE 1, PLANE 0' of 'SUPER BLOCK 200' is included in 'SUPER BLOCK 607.' In other words, after searching the first row of the bad group table, without searching entire columns corresponding a second row and columns corresponding to 'DIE 0' of the third row, it is possible to immediately go to the column corresponding to 'DIE 1, PLANE 0' of the third row, check the first region of the column and confirm that a normal block for replacement is included in 'SUPER BLOCK 607.' A value of 'FFFF' is stored in the second region of the column corresponding to 'DIE 1, PLANE 0' of the third row of the bad group table, and this represents that 'DIE 1, PLANE 0' is the last bad block included in 'SUPER BLOCK 200' as a bad super memory block. Namely, the value of 'FFFF' stored in the second region of each of all the columns of the bad group table means that a bad block does not exist anymore in a bad super memory block indicated by a super block address stored in the first region of a corresponding column. For example, the value of 'FFFF' stored in the second region of a column corresponding to 'DIE 0, PLANE 1' among the plurality of columns corresponding to the first row of the bad group table means that a bad block does not exist anymore after a bad block positioned in 'DIE 0, PLANE 1,' in 'SUPER BLOCK 180' indicated by the super block address stored in the first region of the column corresponding to 'DIE 0, PLANE 1.'

Further, while the value of 'FFFF' is stored in the first region of each of a column corresponding to 'DIE 0, PLANE 0' and a column corresponding to 'DIE 1, PLANE 0' among the plurality of columns corresponding to the first row of the bad group table, this is to represent that 'DIE 0, PLANE 0'

and 'DIE 1, PLANE 0' of 'SUPER BLOCK 145' corresponding to the first row of the bad group table are bad blocks. If the value of 'FFFF' is stored in the first region of a corresponding column in this way, any value may be stored in the second region of the corresponding column. In this regard, it is exemplified in the drawing that a corresponding column is kept empty or is stored with the value of 'FFFF.'

Referring back to FIG. 6, when the controller 130 detects an access request from the host 102 to a super memory block in the memory device 150 at step 615. When an access request to the memory device 150 is received from the host 102, the controller 130 may detect the access request. When the controller 130 tries to access any one among the plurality of super memory blocks included in the memory device 150, according to the access request, a corresponding super memory block may be a bad super memory block. The controller 130 may determine whether the access-requested super memory block is a bad super memory block based on the bad block summary table at step 617. The bad block summary table is generated at step 611. When the controller 130 determines that the access-requested super memory block is a bad super memory block at step 617, the controller 130 may find from the bad group table, which is generated at step 613, the normal blocks mapped to bad blocks included in the access-requested super memory block at step 619. At step 621, the controller 130 may provide an access to the normal blocks of the access-requested super memory block and the victim super memory blocks.

In an embodiment, at step 619 of finding the normal blocks mapped to the bad blocks of the access-requested super memory block from the bad group table, the controller 130 may sequentially scan the location fields on entry-by-entry basis in the bad group table described with reference to FIG. 8B in order to find the address value of the access-requested bad super memory block. When the address value of the access-requested bad super memory block is found, the controller 130 may replace the bad block of the physical location represented by the location field having the address value with the normal block of the same physical location in the victim super memory block in response to the access request for the bad block of the access-requested bad super memory block. As exemplified in FIG. 8B, the controller 130 may replace bad blocks located in the planes 2 and 3 of die 0 in the access-requested bad super memory block 180 with the normal blocks of the same physical location in the victim super memory block 145.

In an embodiment, at step 619, the controller 130 may sequentially scan the first sub-fields of the location fields on entry-by-entry basis in the bad group table described with reference to FIG. 10B in order to find the address value of the access-requested bad super memory block. When the address value of the access-requested bad super memory block is found in a particular first sub-field of a first victim super memory block, the controller 130 may replace the bad block of the physical location represented by the location field of the first sub-field having the address value with the normal block of the same physical location in the first victim super memory block in response to the access request for the bad block of the access-requested bad super memory block. As exemplified in FIG. 10B, the controller 130 may replace a bad block located in the plane 3 of die 1 in the access-requested bad super memory block 200 with the normal blocks of the same physical location in the first victim super memory block 145.

Further, in the embodiment, when the address value of the access-requested bad super memory block is found in a

particular first sub-field of the first victim super memory block, the controller 130 may check the pointer information of the second sub-field included in the same location field as the particular first sub-field. When the pointer information of the second sub-field indicates a physical location of a normal block in a second victim super memory block, the controller 130 may replace the bad block of the physical location represented by the location field of the first sub-field having the address value with the normal block of the same physical location in the second victim super memory block in response to the access request for the bad block of the access-requested bad super memory block. As exemplified in FIG. 10B, due to the pointer information "S3D1P0" in the first victim super memory block 145 indicating the second victim super memory block 607 having the normal block 607 of plane 0 of die 1 mapped to the bad block 200 of the bad super memory block 200 indicated by the first sub-fields included in the same location field as the second sub-field (i.e., the location field representing the normal block 145 of plane 3 of die 0 in the first victim super memory block 145), the controller 130 may replace a bad block located in the plane 0 of die 1 in the access-requested bad super memory block 200 with the normal block 607 of the same physical location in the second victim super memory block 607.

Until the controller 130 finds the second sub-field indicating the pointer information "END", the controller 130 may repeat the checking of the pointer information of the second sub-field and the replacing of the bad block with the normal block based on the pointer information such that the current second victim super memory block is regarded as a next first victim super memory block.

When the second sub-field indicates the pointer information "END", the controller 130 may end step 619. As exemplified in FIG. 10B, due to the pointer information "END" in the victim super memory block 607, the controller 130 may end step 619 and proceed to step 621.

As described above, in the embodiment regarding the bad group table of FIG. 10B, the controller 130 may not have to scan all of the location fields on entry-by-entry basis in the bad group table because of the pointer information included in the second sub-field.

FIG. 11 is a flow chart of an operation of deducing a normal block of a victim super memory block in accordance with an embodiment.

Referring to FIG. 11, it may be seen that, in the case where the bad group table is generated in the scheme described above with reference to FIGS. 7, 8A and 8B, the controller 130 performs an operation of searching the bad group table to deduce a normal block of a victim super memory block for replacing a bad block included in a bad super memory block to which an access request is detected.

In detail, at operations 1111, 1113 and 1117, in order to check where a super block address indicating a bad super memory block to which an access request is detected is stored in the bad group table, the controller 130 may search sequentially the values stored in the bad group table in such a way as to search the plurality of columns included in the first row of the bad group table and then search the plurality of columns included in the second row of the bad group table. While searching, in this way, the values stored in the bad group table sequentially one by one by repeatedly performing the operations 1111, 1113 and 1117, if a super block address indicating a bad super memory block to which an access request is detected is detected, operation 1115 is performed.

Namely, by checking a storage position in the bad group table, searched at the operation 1111, the operation 1113 and

operation 1117, the controller 130 may deduce a normal block of a victim super memory block for replacing a bad block included in a bad super memory block to which an access request is detected.

For example, when assuming by referring to FIG. 8B together that a bad super memory block to which an access request is detected is 'SUPER BLOCK 180,' it may be seen that a first bad block is positioned in 'DIE 0, PLANE 2' of 'SUPER BLOCK 180' as the bad super memory block and a second bad block is positioned in 'DIE 0, PLANE 3' of 'SUPER BLOCK 180' as the bad super memory block. In this state, when performing first the operation 1111 and the operation 1113, it is possible to find that a super block address indicating 'SUPER BLOCK 180' is stored in the first row and the third column of the bad group table. That is to say, because 'DIE 0, PLANE 2' where the first bad block of 'SUPER BLOCK 180' is positioned corresponds to the third column of the bad group table, it is possible to find 'DIE 0, PLANE 2,' by searching the first row of the bad group table at the operation 1111 and the operation 1113 performed first. Since the first row of the bad group table stores a super block address indicating 'SUPER BLOCK 145,' it may be seen that a victim super memory block is 'SUPER BLOCK 145.' Therefore, it is possible to determine, through the operation 1115, that a normal block to be mapped in replacement of the first bad block positioned in 'DIE 0, PLANE 2' of 'SUPER BLOCK 180' as the bad super memory block to which an access request is detected is included in 'SUPER BLOCK 145.'

Then, at the operation 1117, it may be checked that a bad block not mapped to a normal block, that is, the second bad block positioned in 'DIE 0, PLANE 3,' still remains in 'SUPER BLOCK 180' as the bad super memory block to which the access request is detected.

Therefore, by performing second the operation 1111 and the operation 1113, it is possible to find that a super block address indicating 'SUPER BLOCK 180' is stored in the first row and the fourth column of the bad group table. That is to say, because 'DIE 0, PLANE 3' where the second bad block of 'SUPER BLOCK 180' is positioned corresponds to the fourth column of the bad group table, it is possible to find 'DIE 0, PLANE 3,' by searching the first row of the bad group table at the operation 1111 and the operation 1113 performed second. Since the first row of the bad group table stores a super block address indicating 'SUPER BLOCK 145,' it may be seen that a victim super memory block is 'SUPER BLOCK 145.' Therefore, it is possible to determine, through the operation 1115, that a normal block to be mapped in replacement of the second bad block positioned in 'DIE 0, PLANE 3' of 'SUPER BLOCK 180' as the bad super memory block to which the access request is detected is included in 'SUPER BLOCK 145.'

In succession, at the operation 1117, it may be checked that a bad block which is not mapped yet to a normal block does not exist anymore in 'SUPER BLOCK 180' as the bad super memory block to which the access request is detected.

FIG. 12 is a flow chart of an operation of deducing a normal block of a victim super memory block in accordance with another embodiment.

Referring to FIG. 12, it may be seen that, in the case where the bad group table is generated in the scheme described above with reference to FIGS. 9, 10A and 10B, the controller 130 performs an operation of searching the bad group table to deduce a normal block of a victim super memory block for replacing a bad block included in a bad super memory block to which an access request is detected.

In detail, at operations **1211** and **1213**, in order to check where a super block address indicating a bad super memory block to which an access request is detected is stored in the bad group table, the controller **130** may search sequentially the values stored in the bad group table in such a way as to search the first regions of the plurality of columns included in the first row of the bad group table and then search the first regions of the plurality of columns included in the second row of the bad group table. While searching, in this way, the values stored in the bad group table sequentially one by one by repeatedly performing the operations **1211** and **1213**, if a super block address indicating a bad super memory block to which an access request is detected is detected, operation **1215** is performed. After the operation **1215** is performed, the operation **1211** and the operation **1213** are not performed again, and instead, at operation **1217**, it is checked whether coupling information exists in the second region of a column which was a target of the operation **1215**.

That is, by checking a storage position in the bad group table, searched in the operation **1211** and the operation **1213**, the controller **130** may deduce a normal block of a victim super memory block for replacing a first bad block included in a bad super memory block to which an access request is detected. Then, at the operation **1217**, the controller **130** may deduce a normal block of a victim super memory block for replacing at least a second bad block included in the bad super memory block to which the access request is detected.

For example, when assuming by referring to FIG. **10B** together that a bad super memory block to which an access request is detected is 'SUPER BLOCK **200**,' it may be seen that a first bad block is positioned in 'DIE **0**, PLANE **3**' of 'SUPER BLOCK **200**' as the bad super memory block. In this state, when performing first the operation **1211** and the operation **1213**, it is possible to find that a super block address indicating 'SUPER BLOCK **200**' is stored in the first row and the first region of the fourth column of the bad group table. That is to say, because 'DIE **0**, PLANE **3**' where the first bad block of 'SUPER BLOCK **200**' is positioned corresponds to the fourth column of the bad group table, it is possible to find 'DIE **0**, PLANE **3**,' by searching the first row of the bad group table at the operation **1211** and the operation **1213** performed first. Since the first row of the bad group table stores a super block address indicating 'SUPER BLOCK **145**,' it may be seen that a victim super memory block is 'SUPER BLOCK **145**.' Therefore, it is possible to determine, through the operation **1215**, that a normal block to be mapped in replacement of the first bad block positioned in 'DIE **0**, PLANE **3**' of 'SUPER BLOCK **200**' as the bad super memory block to which an access request is detected is included in 'SUPER BLOCK **145**.'

Then, at the operation **1217**, it is checked that which value is stored in the second region of the fourth column of the first row of the bad group table which was a target of the operation **1215**. As a result of the operation **1217**, it may be seen that the value of '3SD0P1' is stored and this is a value indicating the third row and the fifth column of the bad group table. Therefore, by checking, through the operation **1215**, the first region of the fifth column of the third row of the bad group table, it may be seen that a super block address indicating 'SUPER BLOCK **200**' as the bad super memory block is stored. Since the third row of the bad group table stores a super block address indicating 'SUPER BLOCK **607**,' it may be seen that a victim super memory block is 'SUPER BLOCK **607**.' Therefore, it is possible to determine, through the operation **1217**, that the second bad block of 'SUPER BLOCK **200**' as the bad super memory block to which the access request is detected is positioned in 'DIE **1**,

PLANE **0**' and a normal block to be mapped in replacement of the second bad block is included in 'SUPER BLOCK **607**.'

Then, at the operation **1217**, it is checked that which value is stored in the second region of the fifth column of the third row of the bad group table which was a target of the operation **1215**. As a result of the operation **1217**, it may be checked that the value of 'FFFF' is stored and, through this, a bad block which is not mapped yet to a normal block does not exist anymore in 'SUPER BLOCK **200**' as the bad super memory block to which the access request is detected.

Referring again to FIG. **6**, at operation **621**, the controller **130** may provide an access to the bad super memory block of the memory device **150** which is access-requested through the operation **611**.

Hereinbelow, detailed descriptions will be made with reference to FIGS. **13** to **18**, for a data processing system and electronic appliances to which the memory system **110** including the memory device **150** and the controller **130** described above with reference to FIGS. **1** to **12**, according to the embodiment, is applied.

FIG. **13** is a diagram illustrating a data processing system including the memory system according to the embodiment. FIG. **13** is a drawing schematically illustrating a memory card system to which the memory system according to an embodiment is applied.

Referring to FIG. **13**, a memory card system **6100** includes a memory controller **6120**, a memory device **6130**, and a connector **6110**.

In detail, the memory controller **6120** may be connected with the memory device **6130** and may access the memory device **6130**. In some embodiments, the memory device **6130** may be implemented with a nonvolatile memory (NVM). For example, the memory controller **6120** may control read, write, erase and background operations for the memory device **6130**. The memory controller **6120** may provide an interface between the memory device **6130** and a host (not shown), and may drive a firmware for controlling the memory device **6130**. For example, the memory controller **6120** may correspond to the controller **130** in the memory system **110** described above with reference to FIG. **1**, and the memory device **6130** may correspond to the memory device **150** in the memory system **110** described above with reference to FIG. **1**.

Therefore, the memory controller **6120** may include components such as a random access memory (RAM), a processing unit, a host interface, a memory interface and an error correction unit as shown in FIG. **1**.

The memory controller **6120** may communicate with an external device (for example, the host **102** described above with reference to FIG. **1**), through the connector **6110**. For example, as described above with reference to FIG. **1**, the memory controller **6120** may be configured to communicate with the external device through at least one of various communication protocols such as universal serial bus (USB), multimedia card (MMC), embedded MMC (eMMC), peripheral component interconnection (PCI), PCI express (PCIe), Advanced Technology Attachment (ATA), Serial-ATA, Parallel-ATA, small computer system interface (SCSI), enhanced small disk interface (ESDI), Integrated Drive Electronics (IDE), Firewire, universal flash storage (UFS), wireless-fidelity (WI-FI) and Bluetooth. Accordingly, the memory system and the data processing system according to the embodiment may be applied to wired/wireless electronic appliances, For example, a mobile electronic appliance.

The memory device **6130** may be implemented with a nonvolatile memory. For example, the memory device **6130** may be implemented with various nonvolatile memory devices such as an electrically erasable and programmable ROM (EPROM), a NAND flash memory, a NOR flash memory, a phase-change RAM (PRAM), a resistive RAM (ReRAM), a ferroelectric RAM (FRAM) and a spin torque transfer magnetic RAM (STT-MRAM).

The memory controller **6120** and the memory device **6130** may be integrated into a single semiconductor device. For example, the memory controller **6120** and the memory device **6130** may construct a solid state driver (SSD) by being integrated into a single semiconductor device. The memory controller **6120** and the memory device **6130** may construct a memory card such as a PC card (PCMCIA: Personal Computer Memory Card International Association), a compact flash card (CF), a smart media card (SM and SMC), a memory stick, a multimedia card (MMC, RS-MMC, MMCmicro and eMMC), an SD card (e.g., SD, miniSD, microSD and SDHC) and a universal flash storage (UFS).

FIG. **14** is a diagram schematically illustrating an example of a data processing system including a memory system according to an embodiment of the present invention.

Referring to FIG. **14**, a data processing system **6200** includes a memory device **6230** which may be implemented with at least one nonvolatile memory (NVM) and a memory controller **6220** for controlling the memory device **6230**. The data processing system **6200** may be a storage medium such as a memory card (e.g., CF, SD and microSD), as described above with reference to FIG. **1**. The memory device **6230** may correspond to the memory device **150** in the memory system **110** described above with reference to FIG. **1**, and the memory controller **6220** may correspond to the controller **130** in the memory system **110** described above with reference to FIG. **1**.

The memory controller **6220** may control the operations, including the read, write and erase operations for the memory device **6230** in response to requests received from a host **6210**. The memory controller **6220** may include a central processing unit (CPU) **6221**, a random access memory (RAM) as a buffer memory **6222**, an error correction code (ECC) circuit **6223**, a host interface **6224**, and an NVM interface as a memory interface **6225**, all coupled via an internal bus.

The CPU **6221** may control the operations for the memory device **6230** such as read, write, file system management, bad page management, and so forth. The RAM **6222** may operate according to control of the CPU **6221**, and may be used as a work memory, a buffer memory, a cache memory, or the like. In the case where the RAM **6222** is used as a work memory, data processed by the CPU **6221** is temporarily stored in the RAM **6222**. In the case where the RAM **6222** is used as a buffer memory, the RAM **6222** is used to buffer data to be transmitted from the host **6210** to the memory device **6230** or from the memory device **6230** to the host **6210**. In the case where the RAM **6222** is used as a cache memory, the RAM **6222** may be used to enable the memory device **6230** with a low speed to operate at a high speed.

The ECC circuit **6223** corresponds to the ECC unit **138** of the controller **130** described above with reference to FIG. **1**. As described above with reference to FIG. **1**, the ECC circuit **6223** may generate an error correction code (ECC) for correcting a fail bit or an error bit in the data received from the memory device **6230**. The ECC circuit **6223** may per-

form error correction encoding for data to be provided to the memory device **6230**, and may generate data added with parity bits. The parity bits may be stored in the memory device **6230**. The ECC circuit **6223** may perform error correction decoding for data outputted from the memory device **6230**. At this time, the ECC circuit **6223** may correct errors by using the parity bits. For example, as described above with reference to FIG. **1**, the ECC circuit **6223** may correct errors by using various coded modulations such as of a low density parity check (LDPC) code, a Bose-Chaudhuri-Hocquenghem (BCH) code, a turbo code, a Reed-Solomon (RS) code, a convolution code, a recursive systematic code (RSC), a trellis-coded modulation (TCM) and a Block coded modulation (BCM).

The memory controller **6220** transmits and receives data to and from the host **6210** through the host interface **6224**, and transmits and receives data to and from the memory device **6230** through the NVM interface **6225**. The host interface **6224** may be connected with the host **6210** through at least one of various interface protocols such as a parallel advanced technology attachment (PATA) bus, a serial advanced technology attachment (SATA) bus, a small computer system interface (SCSI), a universal serial bus (USB), a peripheral component interconnection express (PCIe) or a NAND interface. Further, as a wireless communication function or a mobile communication protocol such as wireless fidelity (WI-FI) or long term evolution (LTE) is realized, the memory controller **6220** may transmit and receive data by being connected with an external device such as the host **6210** or another external device other than the host **6210**. Specifically, as the memory controller **6220** is configured to communicate with an external device through at least one among various communication protocols, the memory system and the data processing system according to the embodiment may be applied to wired/wireless electronic appliances, For example, a mobile electronic appliance.

FIG. **15** is a diagram illustrating an example of a data processing system including a memory system according to an embodiment of the invention. FIG. **15** may be a solid state drive (SSD).

Referring to FIG. **15**, an SSD **6300** may include a memory device **6340** which may include a plurality of nonvolatile memories NVM, and a controller **6320**. The controller **6320** may correspond to the controller **130** in the memory system **110** described above with reference to FIG. **1**, and the memory device **6340** may correspond to the memory device **150** in the memory system **110** described above with reference to FIG. **1**.

In detail, the controller **6320** may be connected with the memory device **6340** through a plurality of channels CH1, CH2, CH3, . . . , and CHi. The controller **6320** may include a processor **6321**, a buffer memory **6325**, an error correction code (ECC) circuit **6322**, a host interface **6324**, and a nonvolatile memory (NVM) interface as a memory interface **6326** coupled via an internal bus.

The buffer memory **6325** temporarily stores data received from a host **6310** or data received from a plurality of nonvolatile memories NVMs included in the memory device **6340**, or temporarily stores metadata of the plurality of nonvolatile memories NVMs. For example, the metadata may include map data including mapping tables. The buffer memory **6325** may be implemented with a volatile memory such as, but not limited to, a dynamic random access memory (DRAM), a synchronous dynamic random access memory (SDRAM), a double data rate (DDR) SDRAM, a low power double data rate (LPDDR) SDRAM and a graphic random access memory (GRAM) or a nonvolatile

memory such as, but not limited to, a ferroelectric random access memory (FRAM), a resistive random access memory (ReRAM), a spin-transfer torque magnetic random access memory (STT-MRAM) and a phase change random access memory (PRAM). While it is illustrated in FIG. 15, for the sake of convenience in explanation, that the buffer memory 6325 is disposed inside the controller 6320, it is to be noted that the buffer memory 6325 may be disposed outside the controller 6320.

The ECC circuit 6322 calculates error correction code values of data to be programmed in the memory device 6340 in a program operation, performs an error correction operation for data read from the memory device 6340, based on the error correction code values, in a read operation, and performs an error correction operation for data recovered from the memory device 6340 in a recovery operation for failed data.

The host interface 6324 provides an interface function with respect to an external device such as the host 6310. The nonvolatile memory interface 6326 provides an interface function with respect to the memory device 6340 which is connected through the plurality of channels CH1, CH2, CH3, . . . and CHi.

As a plurality of SSDs 6300 to each of which the memory system 110 described above with reference to FIG. 1 is applied are used, a data processing system such as a redundant array of independent disks (RAID) system may be implemented. In the RAID system, the plurality of SSDs 6300 and an RAID controller for controlling the plurality of SSDs 6300 may be included. In the case of performing a program operation by receiving a write command from the host 6310, the RAID controller may select at least one memory system (For example, at least one SSD 6300) in response to the RAID level information of the write command received from the host 6310, among a plurality of RAID levels (for example, the plurality of SSDs 6300) and may output data corresponding to the write command, to the selected SSD 6300. In the case of performing a read operation by receiving a read command from the host 6310, the RAID controller may select at least one memory system (For example, at least one SSD 6300) in response to the RAID level information of the write command received from the host 6310, among the plurality of RAID levels (for example, the plurality of SSDs 6300), and may provide data outputted from the selected SSD 6300, to the host 6310.

FIG. 16 is a diagram illustrating another example of a data processing system including the memory system according to an embodiment of the present invention. FIG. 16 is a drawing schematically illustrating an embedded multimedia card (eMMC) to which a memory system according to an embodiment is applied.

Referring to FIG. 16, an eMMC 6400 includes a memory device 6440 which is implemented with at least one NAND flash memory, and a controller 6430. The controller 6430 may correspond to the controller 130 in the memory system 110 described above with reference to FIG. 1, and the memory device 6440 may correspond to the memory device 150 in the memory system 110 described above with reference to FIG. 1.

In detail, the controller 6430 may be connected with the memory device 6440 through a plurality of channels. The controller 6430 may include a core 6432, a host interface 6431, and a memory interface such as a NAND interface 6433.

The core 6432 may control the operations of the eMMC 6400. The host interface 6431 may provide an interface function between the controller 6430 and a host 6410. The

NAND interface 6433 may provide an interface function between the memory device 6440 and the controller 6430. For example, the host interface 6431 may be a parallel interface such as an MMC interface, as described above with reference to FIG. 1, or a serial interface such as an ultra-high speed class 1 (UHS-I)/UHS class 2 (UHS-II) and a universal flash storage (UFS) interface.

FIG. 17 is a diagram illustrating another example of a data processing system including a memory system according to an embodiment of the present invention. FIG. 16 is a drawing schematically illustrating a universal flash storage (UFS) to which the memory system according to the embodiment is applied.

Referring to FIG. 17, a UFS system 6500 may include a UFS host 6510, a plurality of UFS devices 6520 and 6530, an embedded UFS device 6540, and a removable UFS card 6550. The UFS host 6510 may be an application processor of wired/wireless electronic appliances, for example, a mobile electronic appliance.

The UFS host 6510, the UFS devices 6520 and 6530, the embedded UFS device 6540 and the removable UFS card 6550 may respectively communicate with external devices such as wired/wireless electronic appliances (for example, a mobile electronic appliance), through a UFS protocol. The UFS devices 6520 and 6530, the embedded UFS device 6540 and the removable UFS card 6550 may be implemented with the memory system 110 described above with reference to FIG. 1, for example, as the memory card system 6100 described above with reference to FIG. 13. The embedded UFS device 6540 and the removable UFS card 6550 may communicate through another protocol other than the UFS protocol. For example, the embedded UFS device 6540 and the removable UFS card 6550 may communicate through various card protocols such as, but not limited to, USB flash drives (UFDs), multimedia card (MMC), secure digital (SD), mini SD and Micro SD.

FIG. 18 is a diagram illustrating an example of a data processing system including the memory system according to an embodiment of the present invention. FIG. 18 is a drawing schematically illustrating a user system to which the memory system according to the embodiment is applied.

Referring to FIG. 18, a user system 6600 may include an application processor 6630, a memory module 6620, a network module 6640, a storage module 6650, and a user interface 6610.

The application processor 6630 may drive components included in the user system 6600 and an operating system (OS). For example, the application processor 6630 may include controllers for controlling the components included in the user system 6600, interfaces, graphics engines, and so on. The application processor 6630 may be provided by a system-on-chip (SoC).

The memory module 6620 may operate as a main memory, a working memory, a buffer memory or a cache memory of the user system 6600. The memory module 6620 may include a volatile random access memory such as a dynamic random access memory (DRAM), a synchronous dynamic random access memory (SDRAM), a double data rate (DDR) SDRAM, a DDR2 SDRAM, a DDR3 SDRAM, a low power double data rate (LPDDR) SDRAM, an LPDDR2 SDRAM and an LPDDR3 SDRAM or a nonvolatile random access memory such as a phase change random access memory (PRAM), a resistive random access memory (ReRAM), a magnetic random access memory (MRAM) and a ferroelectric random access memory (FRAM). For example, the application processor 6630 and the memory

module **6620** may be mounted by being packaged on the basis of a package-on-package (POP).

The network module **6640** may communicate with external devices. For example, the network module **6640** may support not only wired communications but also various wireless communications such as code division multiple access (CDMA), global system for mobile communication (GSM), wideband CDMA (WCDMA), CDMA-2000, time division multiple access (TDMA), long term evolution (LTE), worldwide interoperability for microwave access (WiMAX), wireless local area network (WLAN), ultra-wideband (UWB), Bluetooth, wireless display (WI-DI), and so on, and may thereby communicate with wired/wireless electronic appliances. For example, a mobile electronic appliance. According to this fact, the memory system and the data processing system according to the embodiment may be applied to wired/wireless electronic appliances. The network module **6640** may be included in the application processor **6630**.

The storage module **6650** may store data such as data received from the application processor **6530**, and transmit data stored therein, to the application processor **6530**. The storage module **6650** may be realized by a nonvolatile semiconductor memory device such as a phase-change RAM (PRAM), a magnetic RAM (MRAM), a resistive RAM (ReRAM), a NAND flash memory, a NOR flash memory and a 3-dimensional NAND flash memory. The storage module **6650** may be provided as a removable storage medium such as a memory card of the user system **6600** and an external drive. For example, the storage module **6650** may correspond to the memory system **110** described above with reference to FIG. 1, and may be implemented with the SSD, eMMC and UFS described above with reference to FIGS. 15 to 17.

The user interface **6610** may include interfaces for inputting data or commands to the application processor **6630** or for outputting data to an external device. For example, the user interface **6610** may include user input interfaces such as a keyboard, a keypad, a button, a touch panel, a touch screen, a touch pad, a touch ball, a camera, a microphone, a gyroscope sensor, a vibration sensor and a piezoelectric element, and user output interfaces such as a liquid crystal display (LCD), an organic light emitting diode (OLED) display device, an active matrix OLED (AMOLED) display device, a light emitting diode (LED), a speaker and a motor.

In the case where the memory system **110** described above with reference to FIG. 1 is applied to the mobile electronic appliance of the user system **6600** according to an embodiment, the application processor **6630** may control the operations of the mobile electronic appliance, and the network module **6640** as a communication module may control wired/wireless communication with an external device, as described above. The user interface **6610** as the display/touch module of the mobile electronic appliance displays data processed by the application processor **6630** or supports input of data from a touch panel.

According to various embodiments, a memory system may manage a plurality of blocks by grouping them into a plurality of super memory blocks, and use at least any one of the super memory blocks as a victim super memory block. That is to say, the memory system may swap normal blocks of the victim super memory block with bad blocks of remaining super memory blocks. In correspondence to the victim super memory block, the memory system may store mapping information according to the swap of the normal blocks of the victim super memory block with the bad blocks of the remaining super memory blocks. Therefore, the

amount of mapping information in the memory system may be minimized, and a storage space for storing the mapping information may be reduced.

Although various embodiments have been described for illustrative purposes, it will be apparent to those skilled in the art that various changes and modifications may be made without departing from the spirit and scope of the invention as defined in the following claims.

What is claimed is:

1. A memory system comprising:

a memory device including a plurality of memory blocks constituting with a plurality of super memory blocks, wherein each super memory block includes some memory blocks among the plurality of memory blocks; and

a controller suitable for detecting two or more bad super memory blocks each including at least one bad block and at least one normal block, among the super memory blocks, selecting at least one victim super memory block among the two or more bad super memory blocks, and replacing the at least one bad block of each remaining bad super memory blocks with the at least one normal block of the at least one victim super memory block.

2. The memory system of claim 1, wherein the controller generates a bad group table indicating a mapping relationship between the at least one bad block of each of the remaining bad super memory blocks and the at least one normal blocks of the at least one victim super memory block which replace the at least one bad block of each of the remaining bad super memory blocks.

3. The memory system according to claim 2, wherein, in response to a request of access to at least one of the two or more bad super memory blocks, the controller provides access to the at least one normal blocks replacing the at least one bad blocks in the access-requested bad super memory blocks according to the mapping relationship.

4. The memory system according to claim 3,

wherein the controller replaces the at least one bad block of each of the remaining bad super blocks with the at least one normal blocks of the at least one victim super block, having the same physical locations as the at least one bad block of each of the remaining bad super blocks, and

wherein the physical location is of a plane level in the memory device.

5. The memory system according to claim 4,

wherein the bad group table includes at least one entry respectively representing the at least one victim super memory block,

wherein, for the at least one entry, the bad group table includes a plurality of location fields respectively representing physical locations of memory blocks of a corresponding victim super memory block, and

wherein each location field representing the normal block in the at least one victim super memory block has an address value of the remaining bad super memory block having the bad block, which is replaced by the normal block represented thereby.

6. The memory system according to claim 4,

wherein the bad group table includes at least one row and a plurality of columns configured in the form of a matrix, and

wherein, the at least one victim super memory block corresponds to one row, memory blocks included in the at least one victim super memory block correspond to

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the columns, and the at least one bad blocks included in each of remaining bad super memory blocks are mapped to the columns.

7. The memory system according to claim 5, wherein, in response to the request, the controller provides access to the at least one normal blocks replacing the at least one bad blocks in the access-requested bad super memory blocks by: searching the address values of the access-requested bad super memory blocks on an entry-by-entry basis in the bad group table; and identifying the at least one normal blocks replacing the access-requested at least one bad blocks through the physical locations of the at least one normal blocks indicated by the location fields having the address values of the access-requested bad super memory blocks.

8. The memory system according to claim 4, wherein the bad group table includes at least one entry representing the at least one victim super memory block, wherein, for the at least one entry, the bad group table includes a plurality of location fields respectively representing physical locations of memory blocks of the at least one victim super memory block and each location field including first and second sub-fields, wherein the first sub-field, a corresponding location field of which represents the normal block in the at least one victim super memory block, has an address value of the remaining bad super memory block having the bad block, which is replaced by the normal block represented by the corresponding location field, and wherein the second sub-field of the corresponding location field has a pointer information indicating another normal block in another victim super memory block replacing another bad block in the remaining bad super memory block represented by the corresponding location field.

9. The memory system according to claim 8, wherein, in response to a request of access to at least one of the bad super memory blocks, the controller provides the at least one normal blocks replacing the at least one bad blocks in the access-requested bad super memory blocks by: searching the address value of the access-requested bad super memory block on an entry-by-entry basis in the bad group table; identifying a first normal block replacing a first one of the at least one bad blocks in the respective access-requested bad super memory blocks through the physical location of the first normal block indicated by the location field having the address value of the respective access-requested bad super memory blocks in the first sub-field thereof; and identifying respective second and following normal blocks replacing respective second and following ones of the at least one bad blocks in the respective access-requested bad super memory blocks through the physical locations of the respective second and following normal blocks indicated by the location fields corresponding to the respective second and following normal blocks and having the address value of the respective access-requested bad super memory blocks in the first sub-fields of the location fields corresponding to the respective second and following normal blocks via the pointer information in the second sub-fields of the location fields corresponding to the respective first and following normal blocks.

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10. A method for operating a memory system which includes a memory device including a plurality of memory blocks constituting with a plurality of super memory blocks, wherein each super memory blocks includes some memory blocks among the plurality of memory blocks, the method comprising:

detecting two or more bad super memory blocks each including at least one bad block and at least one normal block, among the super memory blocks; selecting at least one victim super memory block among the two or more bad super memory blocks; and replacing the bad blocks of each remaining bad super memory blocks with the at least one normal blocks of the at least one victim super memory block, wherein the replacing includes generating a bad group table indicating a mapping relationship between the at least one bad blocks of the remaining bad super memory blocks and the at least one normal block of the at least one victim super memory block.

11. The method according to claim 10, wherein the replacing includes, in response to a request of access to one or more of the two or more bad super memory blocks, providing access to the at least one normal blocks replacing the at least one bad blocks in the access-requested bad super memory blocks according to the mapping relationship.

12. The method according to claim 11, wherein the at least one bad block of each of the remaining bad super memory blocks are replaced with the at least one normal block of the at least one victim super memory block, having the same physical locations as the at least one bad block of each of the remaining bad super memory blocks, and wherein the physical location is of a plane level in the memory device.

13. The method according to claim 12, wherein the bad group table includes at least one entry respectively representing the at least one victim super memory block, the at least one entry including a plurality of location fields respectively representing physical locations of memory blocks of the at least one victim super memory block, each location field representing the normal block in the at least one victim super memory block having an address value of the remaining bad super memory block having the bad block, which is replaced by the normal block represented thereby.

14. The method according to claim 12, wherein the bad group table includes at least one row and a plurality of columns configured in the form of a matrix, the at least one victim super memory block corresponds to one row, memory blocks included in the at least one victim super memory block correspond to the columns, and the at least one bad blocks included in the remaining bad super memory blocks are mapped to the columns.

15. The method according to claim 13, wherein the providing of access includes: searching the address values of the access-requested bad super memory blocks on an entry-by-entry basis in the bad group table; and identifying the at least one normal blocks replacing the at least one bad blocks in the access-requested bad super memory blocks through the physical locations of the at least one normal blocks indicated by the location fields having the address values of the access-requested bad super memory blocks.

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16. The method according to claim 13,
 wherein the bad group table includes at least one entry
 respectively representing the at least one victim super
 memory block,
 wherein, for the at least one entry, the bad group table 5
 includes a plurality of location fields respectively rep-
 resenting physical locations of memory blocks of the at
 least one victim super memory block and each includ-
 ing first and second sub-fields,
 wherein the first sub-field, a corresponding location field 10
 of which represents the normal block in the at least one
 victim super memory block, has an address value of the
 remaining bad super memory block having the bad
 block, which is replaced by the normal block repre-
 sented by the corresponding location field, and 15
 wherein the second sub-field of the corresponding loca-
 tion field has a pointer information indicating another
 normal block in another victim super memory block
 replacing another bad block in the remaining bad super
 memory block represented by the corresponding loca- 20
 tion field.

17. The method according to claim 16, wherein the
 providing of access includes:
 searching the address value of the access-requested bad
 super memory blocks on an entry-by-entry basis in the 25
 bad group table;
 identifying a first normal block replacing a first one of the
 at least one bad blocks in the respective access-re-
 quested bad super memory blocks through the physical
 location of the first normal block indicated by the 30
 location field having the address value of the respective
 access-requested bad super memory blocks in the first
 sub-field thereof; and
 identifying respective second and following normal
 blocks replacing respective second and following ones 35
 of the at least one bad blocks in the respective access-
 requested bad super memory blocks through the physi-
 cal locations of the respective second and following
 normal blocks indicated by the location fields corre-
 sponding to the respective second and following nor- 40
 mal blocks and having the address value of the respec-
 tive access-requested bad super memory blocks in the

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first sub-fields of the location fields corresponding to
 the respective second and following normal blocks via
 the pointer information in the second sub-fields of the
 location fields corresponding to the respective first and
 following normal blocks.

18. A memory system comprising:
 a memory device including a plurality of dies, each die
 comprising a plurality of planes and each plane com-
 prising a plurality of memory blocks;
 a controller suitable for arranging the plurality of memory
 blocks in a plurality of super memory blocks, detecting
 two or more bad super memory blocks each including
 at least one bad block and at least one normal block,
 among the super memory blocks, selecting at least one
 victim super memory block among the two or more bad
 super memory blocks, and generating a bad group table
 indicating a mapping relationship between the at least
 one bad block of each of the remaining bad super
 memory blocks and the at least one normal blocks of
 the at least one victim super memory block for replac-
 ing the at least one bad block of each of the remaining
 bad super memory blocks with the at least one normal
 blocks of the at least one victim super memory block,
 wherein the plurality of super memory blocks each
 include some memory blocks among the plurality of
 memory blocks.

19. The memory system according to claim 18, wherein,
 in response to a request of access to one or more of the two
 or more bad super memory blocks, the controller provides
 access to the at least one normal blocks replacing the at least
 one bad blocks in the access-requested bad super memory
 blocks according to the mapping relationship.

20. The memory system according to claim 19,
 wherein the controller replaces the at least one bad block
 of each of the remaining bad super memory blocks with
 the at least one normal block of the at least one victim
 super memory block, having the same physical loca-
 tions as the bad blocks in the bad super memory blocks,
 and
 wherein the physical location is of a plane level in the
 memory device.

* * * * *